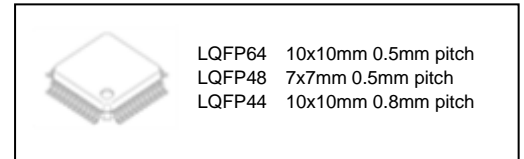


CMOS Digital Integrated Circuit Silicon Monolithic

TMPM4K Group(1)

General Description

- Arm® Cortex®-M4 processor with FPU, Operation frequency: 1 to 120MHz.
Operation voltage: 2.7 to 5.5 V
- Flash memory: 128 to 256 KB.
- Package: 44 to 64 pins, 3 types of packages are available.



Applications

Motors, consumer equipment with motors, and industrial equipment, etc.

Features

- Arm Cortex-M4 processor with FPU
 - Operating frequency: 1 to 120MHz
 - Support Memory Protection Unit (MPU)
- Operating voltage and low-power consumption mode
 - Operating voltage: 2.7 to 5.5V
 - Low-power consumption mode: IDLE mode and STOP1 mode
- Operating temperature: -40 to 105°C
- Internal memory
 - Code flash: 128 to 256 KB, rewrite frequencies: up to 100,000 times
 - RAM: 18KB, support parity
- Clock
 - External high-speed oscillator (EHOSC): 6 to 24MHz (ceramic and crystal oscillator)
 - External high-speed clock input (EHCLKIN): 6 to 24MHz
 - Internal high-speed oscillator (IHOSC1): 10 MHz, support user trimming
 - PLL: 120MHz
- Oscillation frequency detector (OFD): Abnormal system clock detection
- Voltage detection circuit (LVD): 8 levels, Interrupt or reset signal selectale
- Interrupt
 - External factors: 9 to 11 (support digital noise filter)
 - Internal: 78 to 81 factors
- I/O port: 33 to 51 ports
 - Support pull-up and up-down register, open-drain output, and 5V tolerant input
- Onchip debug (JTAG/SW), non-break debug interface (RAM monitor)
- Trigger selection circuit (TRGSEL)
 - Expand trigger request of DMA controller, timer counter and etc.
- DMA controller (DMAC)
 - Trigger requests: 27 to 32 factors by internal and external triggers
- CRC calculation circuit (CRC): 1 channel
 - CRC32 and CRC16
- Asynchronous serial communication circuit (UART): 3 to 4 channels
 - Up to 5Mbps, support FIFO (transmission: 8 stages, reception: 8 stages)
- Serial peripheral interface (TSPI): 2 to 4 channel/s
 - Only SIO mode, up to 20Mbps, support FIFO (transmission: 16 bits × 8 stages, reception: 16 bits × 8 stages)
- I²C Interface
 - I²C Interface (I2C): 1 channel, support multi master
 - I²C Interface version A (EI2C): 1 channel, support multi master and 10-bit addressing
- 12-bit analog to digital converter (ADC): 2 units, 9 to 12 analog inputs
 - Conversion time: 0.73μs at f_{SCLK} = 30MHz
 - Self-diagnosis support function
 - Compare function of conversion results of each unit
- Operational amplifier (OPAMP): 1 unit
 - Gain selectable

Start of commercial production
2024-10

- Advanced programmable motor control circuit (A-PMD): 1 to 2 channels
 - Synchronized operation with 3-phase complementary PWM output and 12-bit ADC
 - PFC: support 3-phase interleaved PFC control
 - Emergency stop function by external inputs (EMG pin, OVV pin)
- Advanced encoder input circuit (32-bit) (A-ENC32): 2 channels
 - Encoder/sensor (3 types)/timer/phase counter mode
- 32-bit timer event counter (T32A)
 - 6 channels as 32-bit timer, 12 channels as 16-bit timer
 - Interval timer, event counter, input capture, 2-phase plus count, PPG output, synchronous start, and trigger start and stop
- Clock selective watchdog timer (SIWDT): 1 channel
 - Clock other than the system clock can be selected as source clock.
 - Clear window, interrupt or reset output selectable

Products Lists Categorized by Functions

The product under development is contained in this table.

For the newest status of each product, Please contact your sales representative.

Table 1 Products Lists

Built-in Functions		TMPM4K4FYBUG TMPM4K4FWBUG	TMPM4K2FYBDUG TMPM4K2FWBDUG	TMPM4K1FYBUG TMPM4K1FWBUG
Memory	Code Flash (KB)	256 128	256 128	256 128
	RAM (KB)	18	18	18
I/O port	PORT (pin)	51	37	33
External interrupt	Factors	11	10	9
	Pins	16	12	11
DMA	DMAC (ch)	32	27	27
Timer function	T32A (ch)	6	6	6
Serial communication function	UART (ch)	4	3	3
	I2C/EI2C (ch)	1 / 1	1 / 1	1 / 1
	TSPI (ch)	4	2	2
Analog function	12-bit ADC (No. of analog input per unit)	12 / 12	10 / 10	9 / 9
	OPAMP (unit)	1	1	1
Motor control function	A-PMD (ch)	2	2	1
	A-ENC32 (ch)	2	2	2
Other function	CRC	1	1	1
	RAMP (ch)	1	1	1
System function	LVD	1	1	1
	SIWDT (ch)	1	1	1
	OFD	1	1	1
	POR	1	1	1
Debug interface	DEBUG	JTAG/SW TRACE(4bits) NBDIF	JTAG/SW	JTAG/SW
Package	Package type	LQFP64 (10 mm x 10 mm, 0.5 mm pitch)	LQFP48 (7 mm x 7 mm, 0.5 mm pitch)	LQFP44 (10 mm x 10 mm, 0.8 mm pitch)
	Package name	P-LQFP64-1010-0.50-003	P-LQFP48-0707-0.50-002	P-LQFP44-1010-0.80-003

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Preface

Conventions

- Numeric formats follow the rules as shown below:

Hexadecimal:	0xABC	
Decimal:	123 or 0d123	- Only when it needs to be explicitly shown that they are decimal numbers.
Binary:	0b111	- It is possible to omit the "0b" when the number of bits can be distinctly understood from a sentence.
- "_N" is added to the end of signal names to indicate low active signals.
- It is called "assert" that a signal moves to its active level, deassert" to its inactive level.
- When two or more signal names are referred, they are described like as [m:n].
 Example: S[3:0] shows four signal names S3, S2, S1 and S0 together.
- The characters surrounded by [] defines the register.
 Example: [ABCD]
- "n" substitutes suffix number of two or more same kind of registers, fields, and bit names.
 Example: [XYZ1], [XYZ2], [XYZ3] → [XYZn]
- "x" substitutes suffix number or character of units and channels in the register list.
- In case of unit, "x" means A, B, and C, ...
 Example: [ADACR0], [ADBCR0], [ADCCR0] → [ADxCR0]
- In case of channel, "x" means 0, 1, and 2, ...
 Example: [T32A0RUNA], [T32A1RUNA], [T32A2RUNA] → [T32AxRUNA]
- The bit range of a register is written like as [m: n].
 Example: Bit[3: 0] expresses the range of bit 3 to 0.
- The configuration value of a register is expressed by either the hexadecimal number or the binary number.
 Example: [ABCD]<EFG> = 0x01 (hexadecimal), [XYZn]<VW> = 1 (binary)
- Word and byte represent the following bit length.

Byte:	8 bits
Half word:	16 bits
Word:	32 bits
Double word:	64 bits
- Properties of each bit in a register are expressed as follows:

R:	Read only
W:	Write only
R/W:	Read and write are possible.
- Unless otherwise specified, register access supports only word access.
- The register defined as "Reserved" must not be rewritten. Moreover, do not use the read value.
- The value read from the bit having default value of "-" is unknown.
- When a register containing both of writable bits and read-only bits is written, read-only bits should be written with their default value, In the cases that default is "-", follow the definition of each register.
- Reserved bits of the write-only register should be written with their default value. In the cases that default is "-", follow the definition of each register.
- Do not use read-modified-write processing to the register of a definition which is different by writing and read out.

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Terms and Abbreviations

Some of abbreviations used in this document are as follows:

ADC	Analog to Digital Converter
A-ENC32	Advanced Encoder Input Circuit (32-bit)
A-PMD	Advanced Programmable Motor Control Circuit
CRC	Cyclic Redundancy Check
DMAC	Direct Memory Access Controller
DNF	Digital Noise Filter
EHOSC	External High-speed Oscillator
EI2C	Inter-integrated Circuit Version A
Fm	Fast Mode of I ² C Interface
IHOSC	Internal High-speed Oscillator
INT	Interrupt
I2C	Inter-integrated Circuit
LVD	Voltage Detection Circuit
NBDIF	Non-break Debug Interface
NMI	Non-maskable Interrupt
OFD	Oscillation Frequency Detector
OPAMP	Operational Amplifier
POR	Power-on Reset Circuit
RAMP	RAM Parity
SIWDT	Clock Selective Watchdog Timer
TRGSEL	Trigger Selection Circuit
TRM	Trimming Circuit
TSPI	Serial Peripheral Interface
T32A	32-bit Timer Event Counter
UART	Asynchronous Serial Communication Circuit

1. Block Diagram

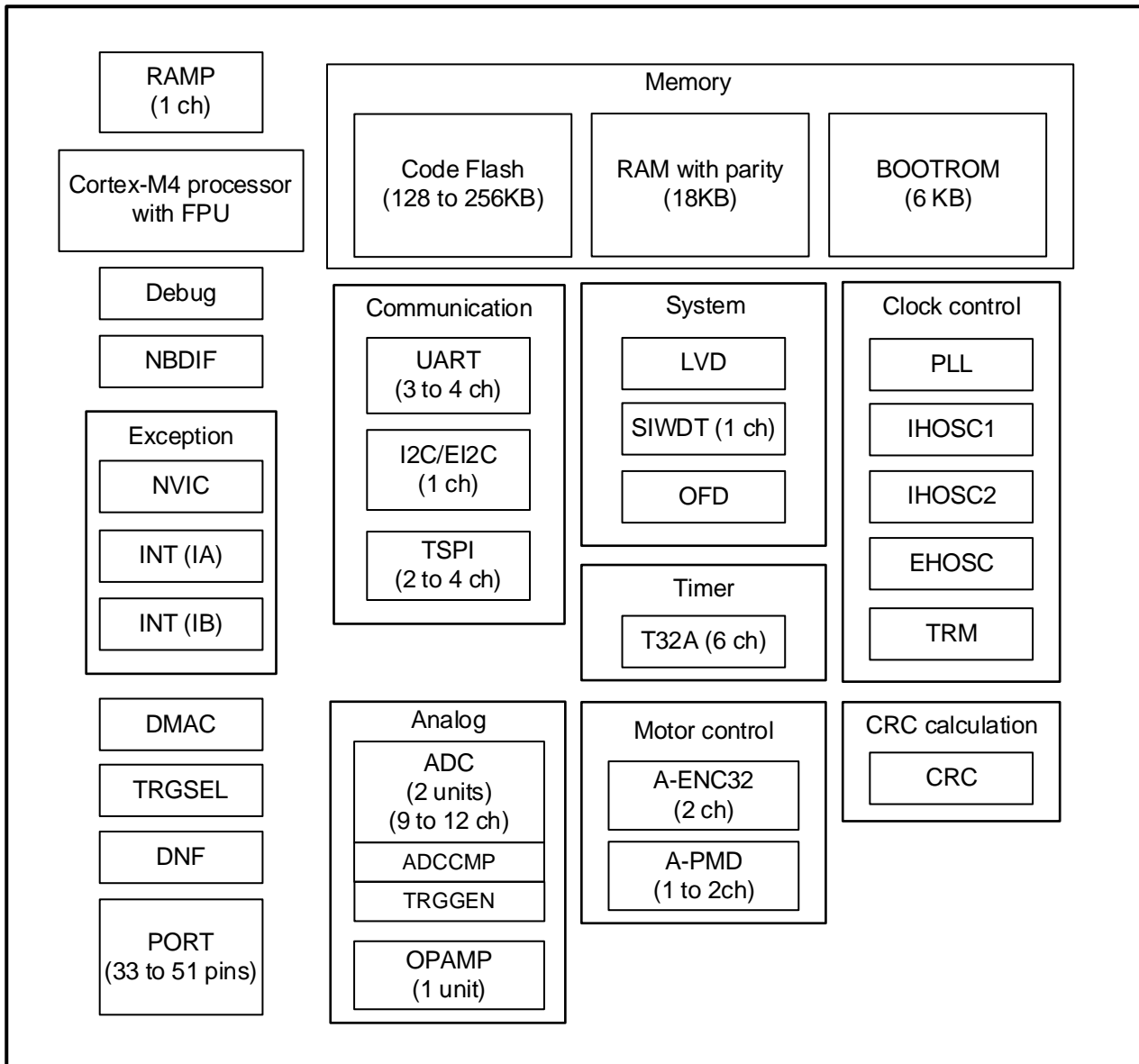
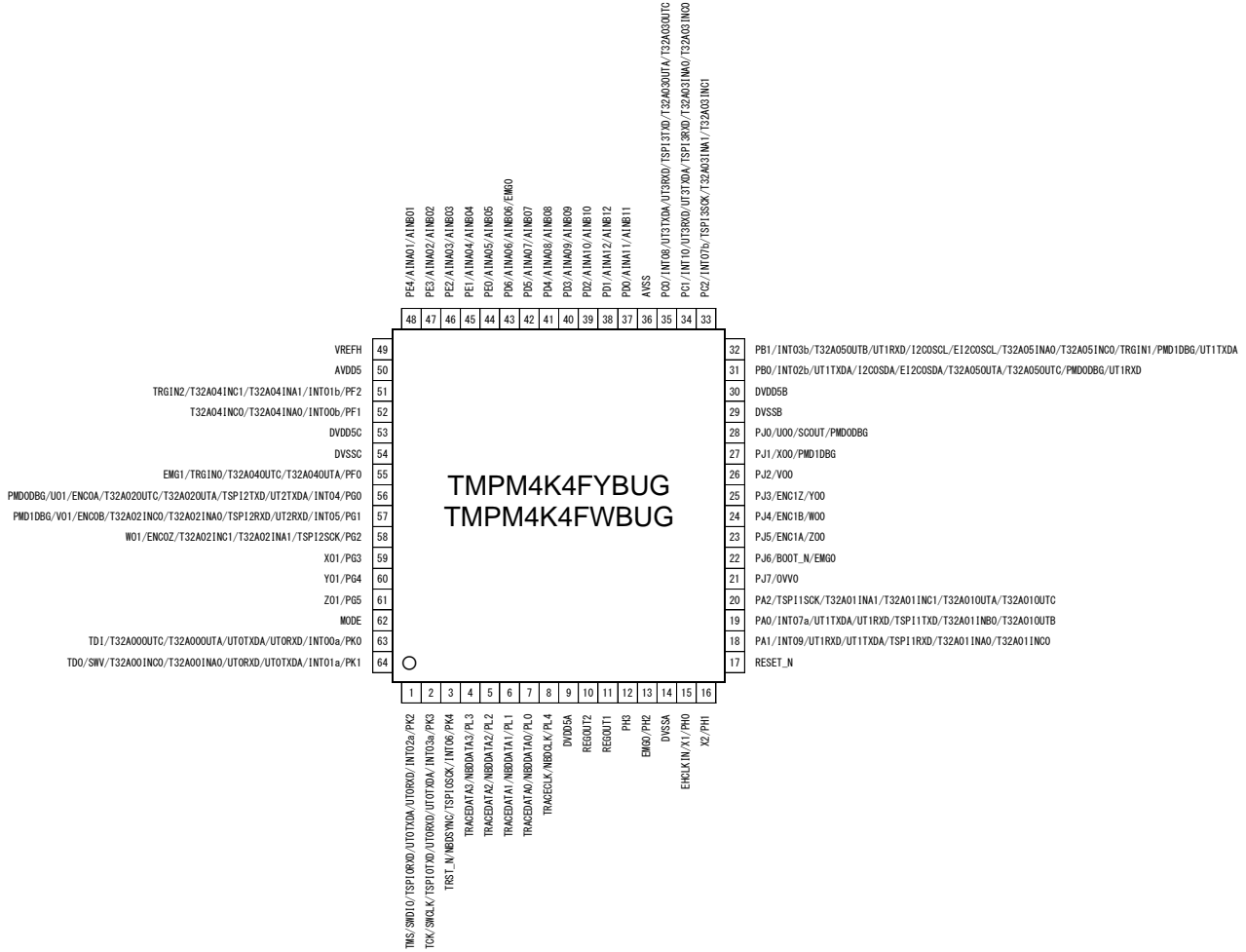


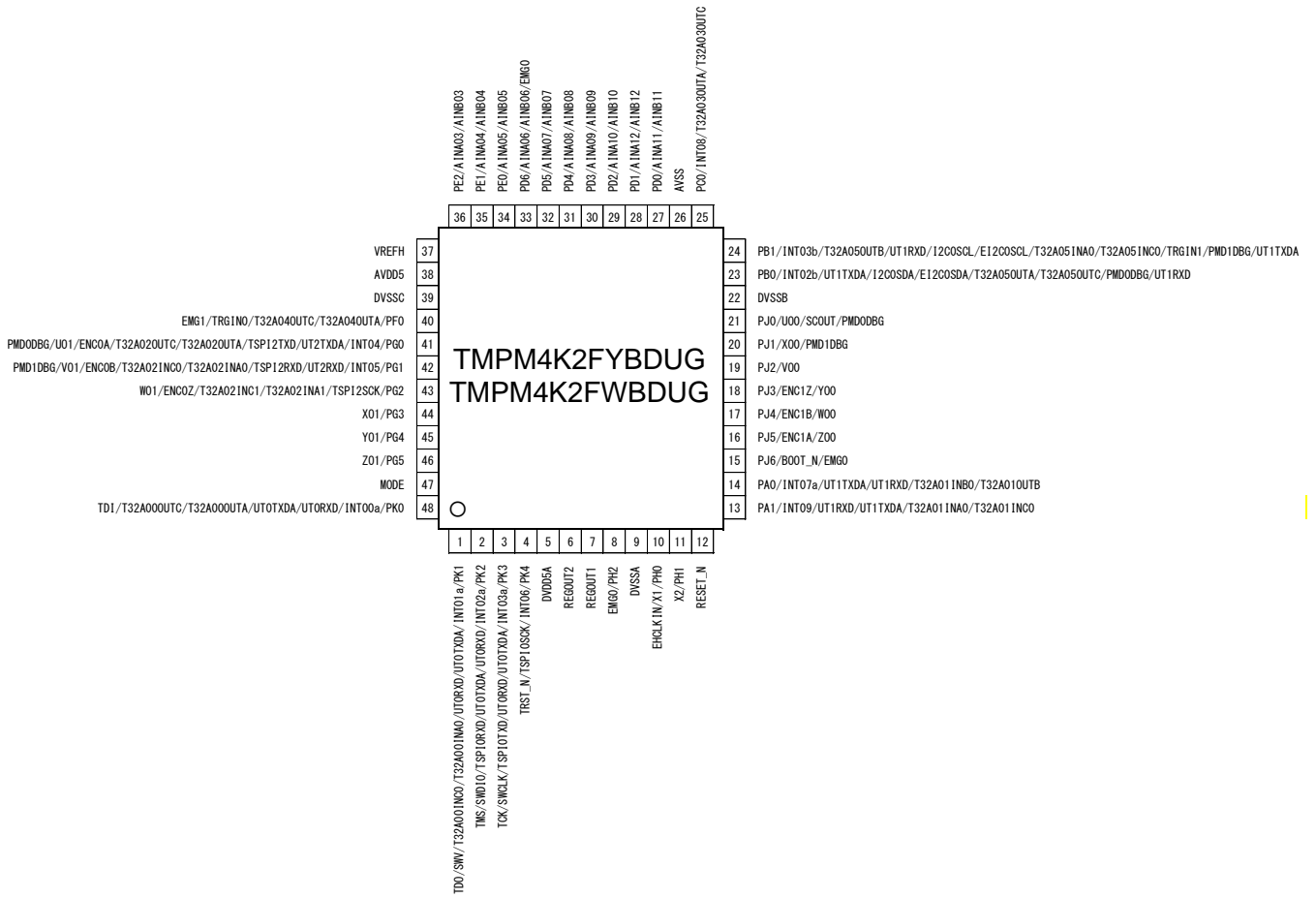
Figure 1.1 Block Diagram of TMPM4K Group(1)

2. Pin Assignment

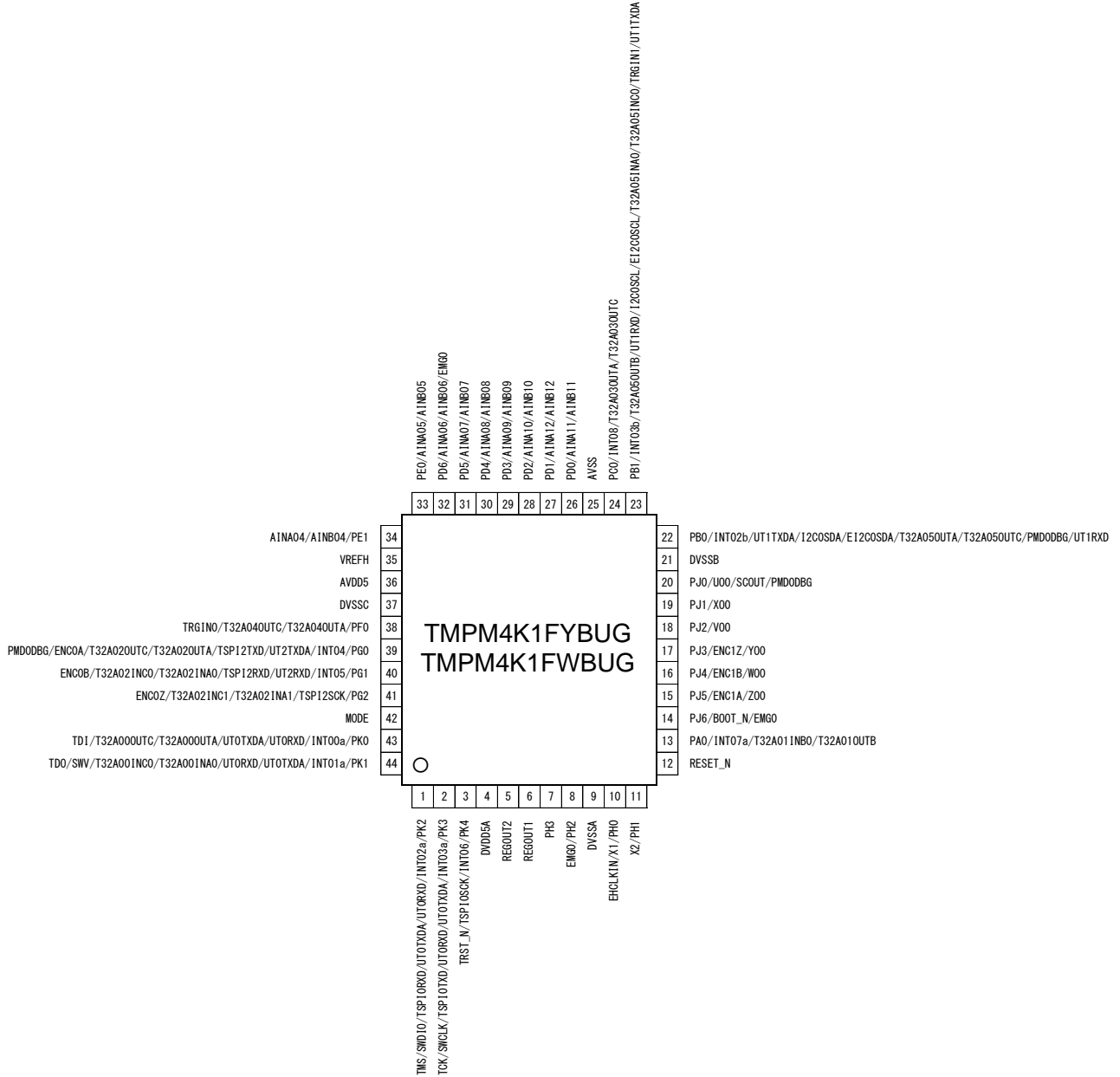
2.1. LQFP64



2.2. LQFP48



2.3. LQFP44



3. Memory Map

0xFFFFFFFF	Vendor-Specific	System level	0xFFFFFFFF	Vendor-Specific	
0xE0100000	CPU Register Region		0xE0100000	CPU Register Region	
0xE0000000	Fault	Peripheral	0xE0000000	Fault	
0x5E040000	Code Flash (Mirror 256KB)		0x5E040000	Code Flash (Mirror 256KB)	
0x5E000000	Flash (SFR)		0x5E000000	Flash (SFR)	
0x5DFF0000	Fault		0x5DFF0000	Fault	
0x44000000	Bit Band Alias (SFR)		0x44000000	Bit Band Alias (SFR)	
0x42000000	Fault		0x42000000	Fault	
0x40100000	SFR		0x40100000	SFR	
0x4003E000	Fault		0x4003E000	Fault	
0x40000000	BOOT ROM		0x40000000	BOOT ROM (Mirror 6KB)	
0x3F7F9800	Fault		0x3F7F9800	Fault	
0x3F7F8000	Fault		0x3F7F8000	Fault	
0x24000000	Bit Band Alias (RAM/Backup RAM)		SRAM	0x24000000	Bit Band Alias (RAM/Backup RAM)
0x22000000	Fault			0x22000000	Fault
0x20004800	RAM2 (10KB)			0x20004800	RAM2 (10KB)
0x20002000	RAM1 (4KB)	0x20002000		RAM1 (4KB)	
0x20010000	RAM0 (4KB)	0x20010000		RAM0 (4KB)	
0x20000000	Fault	0x20000000		Fault	
0x00040000	Code Flash (256KB)	Code	0x00001800	BOOT ROM (6KB)	
0x00000000			0x00000000		

Single chip mode

Single BOOT mode

Figure 3.1 Example of TMPM4KxFYB

Note1: Fault, Reserved: Please do not access their region.

Note2: For details of Single Chip Mode and Single Boot Mode, refer to the Reference Manual "Flash Memory".

3.1. List of Memory Sizes

Table 3.1 Memory Sizes and Addresses

Products			TMPM4K4FYBUG TMPM4K2FYBDUG TMPM4K1FYBUG	TMPM4K4FWBUG TMPM4K2FWBDUG TMPM4K1FWBUG
Peripheral region	Code Flash (Mirror)	Size	256 KB	128 KB
		Start	0x5E000000	0x5E000000
		End	0x5E03FFFF	0x5E01FFFF
SRAM region	RAM	Size	18 KB	
		Start	0x20000000	
		End	0x200047FF	
Code Region	Code Flash	Size	256 KB	128 KB
		Start	0x00000000	0x00000000
		End	0x0003FFFF	0x0001FFFF

4. Pin Description

4.1. Functional Pin Names and Functions

4.1.1. Function Pins of Peripheral

Table 4.1 Functional Pin Names and Functions

Peripheral function	Pin name	Input or Output	Function
Clock control and operation mode (CG)	SCOUT	Output	Output pin for the system clock
Interrupt control (IA/IB)	INTx	Input	External interrupt input pin External input pin provides the noise filter (filter width: typ. 30 ns).
32-bit timer event counter (T32A)	T32AxINA0	Input	16-bit timer A input capture input pin 0
	T32AxINA1	Input	16-bit timer A input capture input pin 1
	T32AxOUTA	Output	16-bit timer A output pin
	T32AxINB0	Input	16-bit timer B input capture input pin 0
	T32AxINB1	Input	16-bit timer B input capture input pin 1
	T32AxOUTB	Output	16-bit timer B output pin
	T32AxINC0	Input	32-bit timer input capture input pin 0
	T32AxINC1	Input	32-bit timer input capture input pin 1
	T32AxOUTC	Output	32-bit timer output pin
Serial peripheral interface (TSPI)	TSPIxRXD	Input	Data input pin
	TSPIxTXD	Output	Data output pin
	TSPIxSCK	I/O	Clock input/output pin
Asynchronous serial communication circuit (UART)	UTxRXD	Input	Data input pin
	UTxTXDA	Output	Data output pin A
I ² C interface (I2C/EI2C)	I2CxSDA/ EI2CxSDA	I/O	Data input/output pin
	I2CxSCL/ EI2CxSCL	I/O	Clock input/output pin
Advanced programmable motor control circuit (A-PMD)	EMGx	Input	Emergency state detection input pin
	OVVx	Input	Overvoltage detection input pin
	UOx	Output	U-phase output pin
	VOx	Output	V-phase output pin
	WOx	Output	W-phase output pin
	XOx	Output	X-phase output pin
	YOx	Output	Y-phase output pin
	ZOx	Output	Z-phase output pin
PMDxDBG	Output	Debug output pin for motor control	
Advanced encoder input circuit (A-ENC32)	ENCxA	Input	Encoder input pin A
	ENCxB	Input	Encoder input pin B
	ENCxZ	Input	Encoder input pin Z
12-bit analog to digital converter (ADC)	AINAx/ AINBx	Input	Analog input pin
Trigger selection circuit (TRGSEL)	TRGINx	Input	External trigger input pin

Note: "x" means channel number, unit number or interrupt number.

4.1.2. Debug Pins

Table 4.2 Debug Pin Names and Functions

Debug PORT	Pin name	Input or Output	Function
JTAG	TMS	Input	JTAG test mode selection input pin
	TCK	Input	JTAG serial clock input pin
	TDO	Output	JTAG serial data output pin
	TDI	Input	JTAG serial data input pin
	TRST_N	Input	JTAG test reset input pin
SW	SWDIO	I/O	Serial wire data input/output pin
	SWCLK	Input	Serial wire clock input pin
	SWV	Output	Serial wire viewer output pin
TRACE	TRACECLK	Output	Trace clock output pin
	TRACEDATA0	Output	Trace data output pin 0
	TRACEDATA1	Output	Trace data output pin 1
	TRACEDATA2	Output	Trace data output pin 2
	TRACEDATA3	Output	Trace data output pin 3
NBDIF	NBDSYNC	Input	Non-break debug synchronous input pin
	NBDCLK	Input	Non-break debug clock input pin
	NBDDATA0	I/O	Non-break debug data input/output pin 0
	NBDDATA1	I/O	Non-break debug data input/output pin 1
	NBDDATA2	I/O	Non-break debug data input/output pin 2
	NBDDATA3	I/O	Non-break debug data input/output pin 3

4.1.3. Control Pins

Table 4.3 Control Pin Names and Functions

	Pin name	Input or Output	Function
Control Pin	X1	Input	High-speed oscillator connection pin
	X2	Output	High-speed oscillator connection pin
	EHCLKIN	Input	External clock input pin
	BOOT_N	Input	BOOT mode control pin The BOOT mode control pin is sampled on the rising edge of the RESET_N pin input. It is not sampled by internal reset factor. If the BOOT mode control pin is "Low" level, the MCU enters single boot mode. If it is "High" level, the MCU enters single chip mode. For details of single boot mode, refer to the Reference Manual "Flash Memory".
	RESET_N	Input	Reset signal input pin
	MODE	Input	Mode Pin This pin must be fixed to "Low" level.

4.1.4. Power Supply Pins

Table 4.4 Power Supply Pin Names and Functions

	Pin name	Function
Power Supply	DVDD5A (Note1) DVDD5B (Note1) DVDD5C (Note1)	Power supply pins for digital DVDD5A/B/C supplies the power to the following pins: PA to PC, PF to PL, MODE, RESET_N
	DVSSA (Note2) DVSSB (Note2) DVSSC (Note2)	GND pins for digital
	REGOUT1 (Note3)	Capacitor for a regulator connection pin (Note4)
	REGOUT2 (Note3)	Capacitor for a regulator connection pin (Note4)
	AVDD5/VREFH	Power supply pin for analog (AVDD5) and reference power pin for analog (VREFH) for analog are assigned to same pin. AVDD5 supplies the power to the following pins: PD, PE
	AVSS	GND pin for analog, this pin is shared with an analog reference GND pin (VREFL).

Note1: Apply same voltage to DVDD5A, DVDD5B, and DVDD5C except the case that the pins are not provided.

Note2: Apply same voltage to DVSSA, DVSSB, and DVSSC except the case that the pins are not provided.

Note3: For REGOUT1 and REGOUT2, do not cause a short circuit with DVDD5A, DVDD5B, or DVDD5C; or DVSSA, DVSSB, or DVSSC.

Note4: For the capacitor value, refer to the "7.14. Regulator".

4.1.5. Capacitors between Power Supply Pins

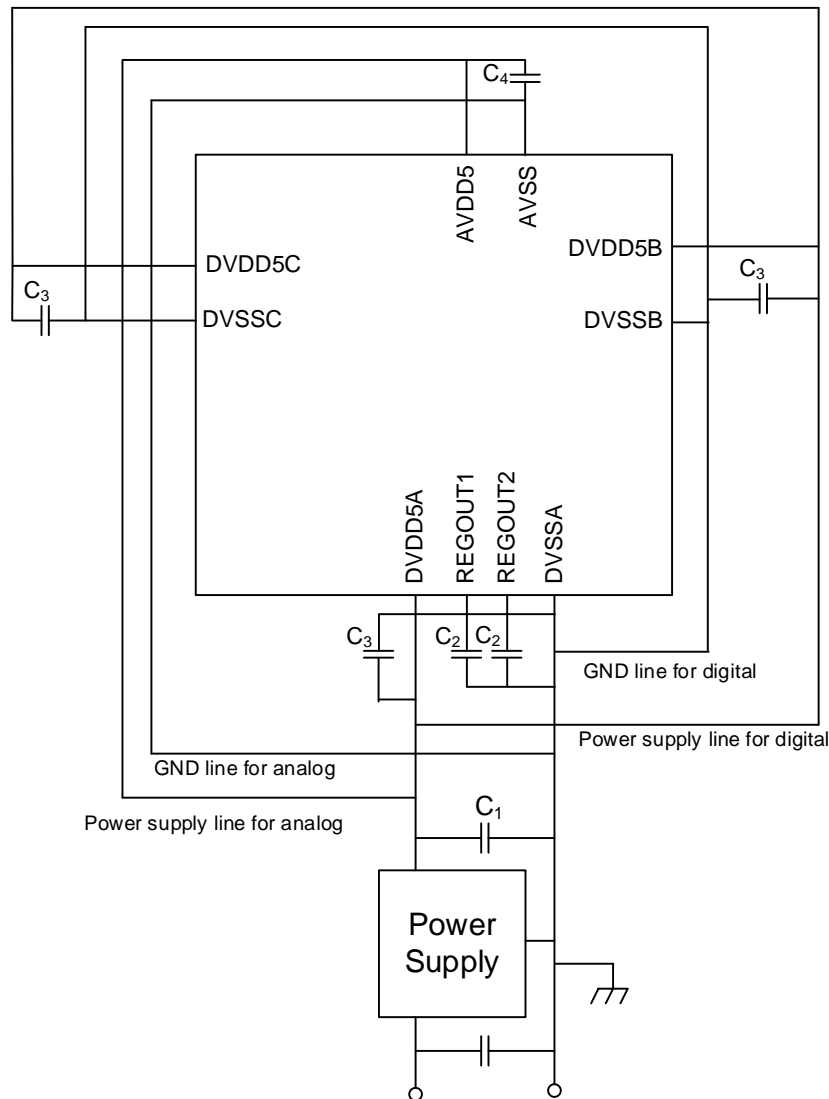


Figure 4.1 Connection Diagram of Capacitors between Power Supply Pins

- Note1: Insert a ceramic capacitor (C_1) near the output pin of the power supply. The power gradient with C_1 must be satisfied V_{PON} and V_{POFF} in "7.5. Characteristics of Internal Processing at RESET".
- Note2: Insert the bypass capacitor ($C_3, C_4:0.01 \mu\text{F}$ to $0.1 \mu\text{F}$) between the power supply and GND near each MCU power supply pin.
- Note3: Insert the power supply stabilizing ceramic capacitor (C_2) of the same capacity into the capacitor connection pin for the internal regulator (REGOUT1, REGOUT2). The capacitor should be placed near DVSSA pin. Regarding value of capacitor, refer to "7.14. Regulator".
- Note4: In order to suppress noise mixing from the power supply for digital to the analog circuit, separate the power supply line for analog and the power supply line for digital near the power supply output pin.
- Note5: In order to suppress noise mixing from the peripheral circuit to the analog circuit, when inserting a filter circuit or pull-up/down resistor to the input/output pin of the analog power supply system, connect the components that make up these circuits to the power supply line for analog.
- Note6: In order to suppress high-frequency noise received from the loop circuit by the power supply line, the GND line, and the capacitor, do not separate the power supply line and the GND line from each other.

4.2. Functional Pins and Ports Assignment (in pin number order)

Following table shows the pin number for each product and the port assignment which were seen from the functional pin.

"-" means that it does not have a pin or there is no assignment of a function.

Table 4.5 Signal Connection List (1/6)

Function	Combination functional pin name	Port Name	M4K4 (LQFP64)	M4K2 (LQFP48)	M4K1 (LQFP44)	
UART ch 0	UT0RXD	PK0	63	48	43	
		PK1	64	1	44	
		PK2	1	2	1	
		PK3	2	3	2	
	UT0TXDA	PK1	64	1	44	
		PK0	63	48	43	
		PK3	2	3	2	
UART ch 1	UT1RXD	PA1	18	13	-	
		PA0	19	14		
		PB0	31	23		22
		PB1	32	24		23
	UT1TXDA	PA0	19	14	-	
		PA1	18	13		
		PB1	32	24		23
		PB0	31	23		22
UART ch 2	UT2RXD	PG1	57	42	40	
	UT2TXDA	PG0	56	41	39	
UART ch 3	UT3RXD	PC1	34	-	-	
		PC0	35			
	UT3TXDA	PC0	35			
		PC1	34			
I2C/EI2C ch 0	I2C0SDA/ EI2C0SDA	PB0	31	23	22	
	I2C0SCL/ EI2C0SCL	PB1	32	24	23	
TSPI ch 0	TSPI0RXD	PK2	1	2	1	
	TSPI0TXD	PK3	2	3	2	
	TSPI0SCK	PK4	3	4	3	
TSPI ch 1	TSPI1RXD	PA1	18	-	-	
	TSPI1TXD	PA0	19			
	TSPI1SCK	PA2	20			
TSPI ch 2	TSPI2RXD	PG1	57	42	40	
	TSPI2TXD	PG0	56	41	39	
	TSPI2SCK	PG2	58	43	41	
TSPI ch 3	TSPI3RXD	PC1	34	-	-	
	TSPI3TXD	PC0	35			
	TSPI3SCK	PC2	33			

Table 4.6 Signal Connection List (2/6)

Function	Combination functional pin name	Port Name	M4K4 (LQFP64)	M4K2 (LQFP48)	M4K1 (LQFP44)
T32A ch 0	T32A00INA0	PK1	64	1	44
	T32A00OUTA	PK0	63	48	43
	T32A00INC0	PK1	64	1	44
	T32A00OUTC	PK0	63	48	43
T32A ch 1	T32A01INA0	PA1	18	13	-
	T32A01INA1	PA2	20	-	-
	T32A01OUTA	PA2	20	-	-
	T32A01INB0	PA0	19	14	13
	T32A01OUTB	PA0	19	14	13
	T32A01INC0	PA1	18	13	-
	T32A01INC1	PA2	20	-	-
	T32A01OUTC	PA2	20	-	-
T32A ch 2	T32A02INA0	PG1	57	42	40
	T32A02INA1	PG2	58	43	41
	T32A02OUTA	PG0	56	41	39
	T32A02INC0	PG1	57	42	40
	T32A02INC1	PG2	58	43	41
	T32A02OUTC	PG0	56	41	39
T32A ch 3	T32A03INA0	PC1	34	-	-
	T32A03INA1	PC2	33	-	-
	T32A03OUTA	PC0	35	25	24
	T32A03INC0	PC1	34	-	-
	T32A03INC1	PC2	33	-	-
	T32A03OUTC	PC0	35	25	24
T32A ch 4	T32A04INA0	PF1	52	-	-
	T32A04INA1	PF2	51	-	-
	T32A04OUTA	PF0	55	40	38
	T32A04INC0	PF1	52	-	-
	T32A04INC1	PF2	51	-	-
	T32A04OUTC	PF0	55	40	38
T32A ch 5	T32A05INA0	PB1	32	24	23
	T32A05OUTA	PB0	31	23	22
	T32A05OUTB	PB1	32	24	23
	T32A05INC0	PB1	32	24	23
	T32A05OUTC	PB0	31	23	22

Table 4.7 Signal Connection List (3/6)

Function	Combination functional pin name	Port Name	M4K4 (LQFP64)	M4K2 (LQFP48)	M4K1 (LQFP44)
12-bit ADC unit A, unit B	AINA11/ AINB11	PD0	37	27	26
	AINA12/ AINB12	PD1	38	28	27
	AINA10/ AINB10	PD2	39	29	28
	AINA09/ AINB09	PD3	40	30	29
	AINA08/ AINB08	PD4	41	31	30
	AINA07/ AINB07	PD5	42	32	31
	AINA06/ AINB06	PD6	43	33	32
	AINA05/ AINB05	PE0	44	34	33
	AINA04/ AINB04	PE1	45	35	34
	AINA03/ AINB03	PE2	46	36	-
	AINA02/ AINB02	PE3	47	-	-
	AINA01/ AINB01	PE4	48	-	-
	INT	INT00a	PK0	63	48
INT00b		PF1	52	-	-
INT01a		PK1	64	1	44
INT01b		PF2	51	-	-
INT02a		PK2	1	2	1
INT02b		PB0	31	23	22
INT03a		PK3	2	3	2
INT03b		PB1	32	24	23
INT04		PG0	56	41	39
INT05		PG1	57	42	40
INT06		PK4	3	4	3
INT07a		PA0	19	14	13
INT07b		PC2	33	-	-
INT08		PC0	35	25	24
INT09		PA1	18	13	-
INT10	PC1	34	-	-	

Table 4.8 Signal Connection List (4/6)

Function	Combination functional pin name	Port Name	M4K4 (LQFP64)	M4K2 (LQFP48)	M4K1 (LQFP44)
A-PMD ch 0	EMG0	PJ6	22	15	14
		PD6	43	33	32
		PH2	13	8	8
	OVV0	PJ7	21	-	-
	UO0	PJ0	28	21	20
	VO0	PJ2	26	19	18
	WO0	PJ4	24	17	16
	XO0	PJ1	27	20	19
	YO0	PJ3	25	18	17
	ZO0	PJ5	23	16	15
	PMD0DBG	PB0	31	23	22
		PG0	56	41	39
		PJ0	28	21	20
A-PMD ch 1	EMG1	PF0	55	40	-
	UO1	PG0	56	41	-
	VO1	PG1	57	42	-
	WO1	PG2	58	43	-
	XO1	PG3	59	44	-
	YO1	PG4	60	45	-
	ZO1	PG5	61	46	-
	PMD1DBG	PB1	32	24	-
		PJ1	27	20	-
PG1		57	42	-	
A-ENC32 ch 0	ENC0A	PG0	56	41	39
	ENC0B	PG1	57	42	40
	ENC0Z	PG2	58	43	41
A-ENC32 ch 1	ENC1A	PJ5	23	16	15
	ENC1B	PJ4	24	17	16
	ENC1Z	PJ3	25	18	17

Table 4.9 Signal Connection List (5/6)

Function	Combination functional pin name	Port Name	M4K4 (LQFP64)	M4K22 (LQFP48)	M4K1 (LQFP44)
TRGSEL	TRGIN0	PF0	55	40	38
	TRGIN1	PB1	32	24	23
	TRGIN2	PF2	51	-	-
JTAG/SW	TMS	PK2	1	2	1
	TCK	PK3	2	3	2
	TDO	PK1	64	1	44
	TDI	PK0	63	48	43
	TRST_N	PK4	3	4	3
	SWDIO	PK2	1	2	1
	SWCLK	PK3	2	3	2
	SWV	PK1	64	1	44
TRACE	TRACECLK	PL4	8	-	-
	TRACEDATA0	PL0	7		
	TRACEDATA1	PL1	6		
	TRACEDATA2	PL2	5		
	TRACEDATA3	PL3	4		
NBDIF	NBDSYNC	PK4	3	-	-
	NBDCLK	PL4	8		
	NBDDATA0	PL0	7		
	NBDDATA1	PL1	6		
	NBDDATA2	PL2	5		
	NBDDATA3	PL3	4		

Table 4.10 Signal Connection List (6/6)

Function	Pin name	Port name	M4K4 (LQFP64)	M4K2 (LQFP48)	M4K1 (LQFP44)
Input/output port	PH3		12	-	7
Control pin	X1	PH0	15	10	10
	X2	PH1	16	11	11
	EHCLKIN	PH0	15	10	10
	SCOUT	PJ0	28	21	20
	BOOT_N	PJ6	22	15	14
	RESET_N		17	12	12
	MODE		62	47	42
Power supply pin	VREFH		49	37	35
	AVDD5		50	38	36
	AVSS		36	26	25
	DVDD5A		9	5	4
	DVDD5B		30	-	-
	DVDD5C		53	-	-
	DVSSA		14	9	9
	DVSSB		29	22	21
	DVSSC		54	39	37
	REGOUT1		11	7	6
	REGOUT2		10	6	5

4.3. Ports

The symbols of each table of the port have the following meanings.

- Input/Output: Input or/and output of port
 - Input: Input port
 - Output: Output port
 - I/O: Input/Output port

- PU/PD: Programmable pull-up or/and pull-down register
 - PU: Programmable pull-up resistor can be enabled.
 - PD: Programmable pull-down resistor can be enabled.

- OD: Programmable open-drain output
 - Yes: Supported
 - No: Not supported

- 5V_T: 5V-tolerant input
 - Yes: Supported
 - N/A: Not available

- SMT/CMOS: Input gate
 - SMT: Schmitt trigger input
 - CMOS: CMOS input

- Under Reset: Port state under reset
 - Hi-Z: High impedance
 - PU: Pull-up resistor enabled
 - PD: Pull-down resistor enabled

- After Reset: Port state after reset
 - Hi-z: High impedance
 - PU: Pull-up resistor enabled
 - PD: Pull-down resistor enabled

4.3.1. Port Specification Table

Table 4.11 Port Names and Specifications of Port A, B, C, D, E, F, G

Port Name	Input/Output	PU/PD	OD	5V_T	SMT/CMOS	Under Reset	After Reset
PA0	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PA1	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PA2	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PB0	Input/Output	PU/PD	YES	YES	SMT	Hi-Z	Hi-Z
PB1	Input/Output	PU/PD	YES	YES	SMT	Hi-Z	Hi-Z
PC0	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PC1	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PC2	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PD0	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PD1	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PD2	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PD3	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PD4	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PD5	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PD6	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PE0	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PE1	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PE2	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PE3	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PE4	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PF0	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PF1	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PF2	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PG0	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PG1	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PG2	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PG3	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PG4	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PG5	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z

Table 4.12 Port Names and Specifications of Port H, J, K, L

Port Name	Input/Output	PU/PD	OD	5V_T	SMT/CMOS	Under Reset	After Reset
PH0	Input	PD	N/A	N/A	SMT	Hi-Z	Hi-Z
PH1	Input	PD	N/A	N/A	SMT	Hi-Z	Hi-Z
PH2	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PH3	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PJ0	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PJ1	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PJ2	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PJ3	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PJ4	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PJ5	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PJ6	Input/Output	PU/PD (Note1)	YES	N/A	SMT	PU	Hi-Z
PJ7	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PK0	Input/Output	PU/PD	YES	N/A	SMT	PU (Note2)	PU (Note2)
PK1	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z (Note2)	Hi-Z Note2
PK2	Input/Output	PU/PD	YES	N/A	SMT	PU (Note2)	PU (Note2)
PK3	Input/Output	PU/PD	YES	N/A	SMT	PD (Note2)	PD (Note2)
PK4	Input/Output	PU/PD	YES	N/A	SMT	PU (Note2)	PU (Note2)
PL0	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PL1	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PL2	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PL3	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z
PL4	Input/Output	PU/PD	YES	N/A	SMT	Hi-Z	Hi-Z

Note1: PJ6 is combination with BOOT_N. When RESET_N pin is "Low" level, pull-up resistor of PJ6 is connected.

When RESET_N pin is "High" level, PJ6 state is Hi-Z with internal reset.

Note2: It is assigned to a debugging pin in the state of the initial stage.

(PK0: TDI, PK1: TDO/SWV, PK2: TMS/SWDIO, PK3: TCK/SWCLK, PK4: TRST_N)

After receiving the command from TOOL, PK1: TDO/SWV becomes output.

5. Functional Description and Operation Description

5.1. Reference Manuals

For more information of built-in functions on TMPM4K Group(1), refer to the Reference Manuals below;

Table 5.1 Reference Manuals for TMPM4K Group(1)

Reference Manual	IP Symbol	Category
Input/Output Ports (TMPM4K Group(1))	PORT-M4K(1)	System
Exception (TMPM4K Group(1))	EXCEPT-M4K(1)	System
Clock Control and Operation Mode (TMPM4K Group(1))	CG-M4K(1)-E	System
Product Information (TMPM4K Group(1))	PINFO-M4K(1)	System
Flash Memory	FLASH256U2-A	Peripheral
Trimming Circuit	TRM-B	Peripheral
Oscillation Frequency Detector	OFD-A	Peripheral
Voltage Detection Circuit	LVD-D	Peripheral
Digital Noise Filter Circuit	DNF-A	Peripheral
Debug Interface	DEBUG-A	Peripheral
Non-break debug Interface	NBDIF-A	Peripheral
DMA Controller	DMAC-B	Peripheral
Asynchronous Serial Communication Circuit	UART-C	Peripheral
Serial Peripheral Interface	TSPI-E	Peripheral
I ² C Interface	I2C-B	Peripheral
I ² C Interface version A	EI2C-A	Peripheral
12-bit Analog to Digital Converter	ADC-G2	Peripheral
Operational Amplifier	OPAMP-B	Peripheral
Advanced Programmable Motor Control Circuit	A-PMD-A	Peripheral
Advanced Encoder Input Circuit (32-bit)	A-ENC32-A	Peripheral
32-bit Timer Event Counter	T32A-C	Peripheral
Clock Selective Watchdog Timer	SIWDT-A	Peripheral
CRC Calculation Circuit	CRC-A	Peripheral
RAM Parity	RAMP-B	Peripheral

5.2. Processor Core

The TPM4K Group(1) incorporates a high-performance 32-bit processor core (Arm Cortex-M4 processor with FPU).

For the operation of the processor core, refer to the Arm documentation set for "Cortex-M series processors". This section explains the product-specific information.

5.2.1. Core Information

The Cortex-M4 processor with FPU revision used in the TPM4K Group(1) is shown as below:

For details of the CPU core and the architecture, refer to the Arm documentation on Arm's website.

Table 5.2 Core Revision

Group name	Core revision
TPM4K Group(1)	r0p1

5.2.2. Configurable Options

In the Cortex-M4 processor with FPU, some blocks can be selected to implement. The following table shows the configurations of the TPM4K Group(1).

Table 5.3 Configurable Options and Their Implementations

Configurable option	Implementation
FWB	Literal comparator: 2 Instruction comparator: 6
DWT	Comparator: 4
ITM	Available
MPU	Available
ETM	Available
AHB-AP	Available
AHB trace macro cell interface	Not available
TPIU	Available
WIC	Not available
Debug port	JTAG/Serial wire
Bit band	Available
Sequential control of AHB	Not available

5.3. Clock Control and Operating Mode (CG)

The clock control and operating mode (CG) selects a clock gear ratio and the prescaler clock, or warm-up time of the oscillator.

There are NORMAL mode and low-power consumption mode as operating modes. Power consumption can be decreased by operating mode transition for use purposes.

The outline of the clock/mode control circuit is as follows:

- Internal high-speed oscillator (IHOSC1): 10MHz
- Selectable from the external high-speed oscillator (EHOSC) or internal high-speed oscillator (IHOSC1).
- Clock multiplication circuit (PLL):
For system clock, capable of 120MHz output by changing the multiplication ratio according to fosc.
- Clock gear:
The high-speed clock can be divided by 1, 2, 4, 8, or 16 and used as the system clock (fsys).
- Low-power consumption mode:
IDLE mode: Only CPU is stopped. The operation of each peripheral circuit can be enabled or disabled.
STOP1 mode: fsys is stopped.

5.4. Flash Memory (256KB/128KB)

The cord flash stores instruction code, and CPU reads instruction code and executes.

It has protection function which prohibits write or erase by the block unit and security function which prohibits the reading of the program code by the 3rd person.

5.5. Oscillator

- External high-speed oscillator (EHOSC): Pins of EHOSC are connected crystal resonator or ceramic resonator. Use as clock source for system clock (fsys).
- Internal high-speed oscillator 1 (IHOSC1): The oscillation frequency is 10MHz. Use as clock source for system clock (fsys).
- Internal high-speed oscillator 2 (IHOSC2): The oscillation frequency is 10MHz. Use as the reference clock of OFD and clock source of SIWDT.

Table 5.4 Built-in Oscillator

Oscillator	M4K4	M4K2	M4K1
EHOSC	✓	✓	✓
IHOSC1	✓	✓	✓
IHOSC2	✓	✓	✓

Note: ✓: Available, -: N/A

5.6. Trimming Circuit (TRM)

The trimming circuit (TRM) can adjust oscillation frequency of the internal high-speed oscillator 1 (IHOSC1).

Table 5.5 Built-in TRM

	M4K4	M4K2	M4K1
TRM	✓	✓	✓

Note: ✓: Available, -: N/A

5.7. Oscillation Frequency Detector (OFD)

The oscillation frequency detector (OFD) can detect an abnormal system clock. The external high-speed clock (f_{EHOSC}) or high-speed clock (f_c) can be selected as the target of detection.

The selected clock is measured by the internal high-speed oscillator 2 (IHOSC2) which is used as the reference clock of OFD. If the clock frequency of f_{EHOSC} or f_c is out of the specified range, a reset signal occurs.

The upper limit and lower limit of detection frequency ranges can be specified respectively.

Table 5.6 Built-in OFD

	M4K4	M4K2	M4K1
OFD	✓	✓	✓

Note: ✓: Available, -: N/A

5.8. Voltage Detection Circuit (LVD)

The voltage detection circuit (LVD) detects whether a power-supply voltage is lower or higher than the preset voltage. When a lower or higher voltage than the preset voltage is detected, the LVD generates an interrupt request or internal reset signal.

Setting voltage can be selected from eight voltages. The LVD is set to enable from resetting when the power supply is turned on.

Table 5.7 Built-in LVD

	M4K4	M4K2	M4K1
LVD	✓	✓	✓

Note: ✓: Available, -: N/A

5.9. Digital Noise Filter Circuit (DNF)

The digital noise filter circuit (DNF) can eliminate the noise of signal from an external interrupt input pin. The high and low noise from an external interrupt signal INTx is eliminated.

Table 5.8 Number of External Interrupt (Number of Built-in DNF)

	M4K4	M4K2	M4K1
Number of External Interrupt	11	10	9

5.10. Debug Interface (DEBUG)

The serial wire debug ports (SWCLK and SWDIO) and the JTAG debug ports (TDI, TDO, TMS, TCK, and TRST_N) use for the interface for connecting debug tool. These pins are connected with the debug tool and used for the program development. And also the trace clock (TRACECLK), trace outputs (TRACEDATA0 to 3) and the NBDIF (NBDSYNC, NBDCLK, and NBDDATA0 to 3) are used to reduce the debug process.

TMPM4K Group(1) products support the serial wire debug ports, JTAG debug ports, trace clock and trace outputs, and NBDIF.

Table 5.9 Built-in Debug Interface

Pin names	PORT	M4K4	M4K2	M4K1
TMS/SWDIO	PK2	✓	✓	✓
TCK/SWCLK	PK3	✓	✓	✓
TDO/SWV	PK1	✓	✓	✓
TDI	PK0	✓	✓	✓
TRST_N	PK4	✓	✓	✓
TRACECLK	PL4	✓	-	-
TRACEDATA0	PL0	✓	-	-
TRACEDATA1	PL1	✓	-	-
TRACEDATA2	PL2	✓	-	-
TRACEDATA3	PL3	✓	-	-
NBDSYNC	PK4	✓	-	-
NBDCLK	PL4	✓	-	-
NBDDATA0	PL0	✓	-	-
NBDDATA1	PL1	✓	-	-
NBDDATA2	PL2	✓	-	-
NBDDATA3	PL3	✓	-	-

Note: ✓: Available, -: N/A

5.10.1. Non-break Debug Interface (NBDIF)

Connecting the debug tools which support Non-break Debug Interface (NBDIF) can provide RAM monitor, etc. Supporting the NBDIF varies depending on the product. Refer to "Table 5.9 Built-in Debug Interface".

5.11. DMA Controller (DMAC)

The DMA controller (DMAC) is the peripheral function to move the data between peripheral function and the memory, or between memories. These operations are performed separately from the CPU control; thus, the CPU load can be greatly reduced by using the DMA.

TMPM4K Group(1) products have one unit of DMAC. One DMAC has the DMA requests of the 32 channels.

Table 5.10 Built-in DMAC

DMAC	M4K4	M4K2	M4K1
Unit A	✓	✓	✓

Note: ✓: Available, -: N/A

5.12. Asynchronous Serial Communication Circuit (UART)

The asynchronous serial communication circuit (UART) is asynchronous serial communication function. It can select the data length of 7, 8 or 9 bits, use or not use parity bit, and a STOP bit length of 1 or 2 bits. Moreover, selection of the MSB first/LSB first, data signal polarity can be performed and pin exchanged of UTxTXDA/UTxRXD can be performed by a port setting.

The FIFO buffer supports data communication on 9 bits × 8 stages at transmission; and on 9 bits × 8 stages at reception.

Table 5.11 Built-in UART

UART	M4K4	M4K2	M4K1
Channel 0	✓	✓	✓
Channel 1	✓	✓	✓
Channel 2	✓	✓	✓
Channel 3	✓	-	-

Note1: ✓: Available, -: N/A

Note2: External pins vary depending on the product. Refer to "2. Pin Assignment".

5.13. Serial Peripheral Interface (TSPI)

The serial peripheral interface (TSPI) on TPM4K Group(1) products supports only SIO mode which does not use a CS signal. It performs the serial communication with other device at high speed.

It can change the data length from 7 bits with a parity bit to 32 bits without a parity bit on a per bit basis

The TSPI has the reception and transmission 16-bit FIFO on 8 stages. The TSPI on TPM4K Group(1) products supports the master device operation and slave device operation.

The TSPI can use the frame mode (frame length: 8 to 32 bits) or sector mode (sector length: 2 to 4 sectors and frame length: 8 to 128 bits).

Table 5.12 Built-in TSPI

TSPI	M4K4	M4K2	M4K1
Channel 0	✓	✓	✓
Channel 1	✓	-	-
Channel 2	✓	✓	✓
Channel 3	✓	-	-

Note1: ✓: Available, -: N/A

Note2: External pins vary depending on the product. Please refer to section "2 Pin Assignment".

5.14. I²C Interface

The following table shows the list of built-in I²C interface (I2C/EI2C).

The I2C and EI2C must be used exclusively.

Table 5.13 Built-in I2C/EI2C

I2C/EI2C	M4K4	M4K2	M4K1
Channel 0	✓	✓	✓

Note1: ✓: Available, -: N/A

Note2: External pins vary depending on the product. Please refer to "2. Pin Assignment".

5.14.1. I²C Interface (I2C)

The I²C interface (I2C) is two-wire bidirectional serial communications between the master and slave devices. The I2C supports the multi-master bus which two or more master devices on the same bus in.

And also, it supports standard-mode (transfer speed: up to 100kHz), fast-mode (transfer speed: up to 400kHz). Its addressing mode supports 7-bit addressing.

5.14.2. I²C Interface Version A (EI2C)

The I²C Interface version A (EI2C) is compatible with two-wire bidirectional serial communications of I²C interface between the master and slave devices. The EI2C supports the multi-master bus which two or more master devices on the same bus in.

And also, it supports standard-mode (transfer speed: up to 100kHz), fast-mode (transfer speed: up to 400kHz), and fast-mode Plus (transfer speed: up to 1MHz) . Its addressing mode supports 7-bit and 10-bit addressing.

5.15. 12-bit Analog to Digital Converter (ADC)

The 12-bit analog to digital converter (ADC) is a successive-approximation analog-to-digital converter. The combination of conversion result register and analog input can be programmed for each AD conversion start factor.

The AD conversion start factor is selected from a software or the peripheral functions (trigger output of A-PMD, timer/event counter output, port input, or trigger generation circuit).

The monitor function is available and it can generate an interrupt request when the compare conditions are matched.

The ADC incorporates a selector to connect VREFH/VREFL with reference power supply. Controlling by software can support self-diagnosis function.

Table 5.14 Number of Analog Inputs

	M4K4	M4K2	M4K1
Number of analog inputs (Unit A)	12	10	9
Number of analog inputs (Unit B)	12	10	9

Note: External pins vary depending on the product. Please refer to "2. Pin Assignment".

There are two functions that can be used with the ADC.

- AD conversion result comparison circuit (ADCCMP)
 The ADCCMP compares the conversion results of the two units. If the compared result is setting value beforehand or more, it generates an interrupt.
- Trigger generation circuit (TRGGEN)
 TRGGEN outputs a trigger signal to start the conversion.

For information on ADCCMP and TRGGEN, refer to the section "12-bit Analog to Digital Converter (ADC)" in the reference manual "Product Information".

5.16. Operational Amplifier (OPAMP)

The operation amplifier (OPAMP) can amplify a weak analog signal in order to input to the ADC. The gain of OPAMP can be selectable.

Table 5.15 Built-in OPAMP

OPAMP	M4K4	M4K2	M4K1
Unit A	✓	✓	✓

Note: ✓: Available, -: N/A

5.17. Advanced Programmable Motor Control Circuit (A-PMD)

The advanced programmable motor control circuit (A-PMD) controls the brushless DC motors easily. It incorporates the pulse modulation circuit and dead-time circuit, and easily generates waveforms for motor control by coordinating with the 3-phase complementary PWM and ADC.

It also provides the over-voltage detection input and abnormal detection input to support safety measures.

Furthermore, it can provide the 3-phase interleaved PFC control for power factor improvement.

Table 5.16 Built-in A-PMD

A-PMD	M4K4	M4K2	M4K1
Channel 0	✓	✓	✓
Channel 1	✓	✓	-

Note1: ✓: Available, -: N/A

Note2: External pins vary depending on the product. Refer to section "2. Pin Assignment".

5.18. Advanced Encoder Input Circuit (32-bit) (A-ENC32)

The advanced encoder input circuit (32-bit) (A-ENC32) supports an incremental encoder to acquire the motor position easily. The noise canceller is built-in the signal input pin of A-ENC32, so that the signals from an incremental encoder or Hall sensor can be input directly.

The A-ENC32 provides six operating modes: encoder mode, sensor modes (3 types), timer mode, and phase counter mode.

Table 5.17 Built-in A-ENC32

A-ENC32	M4K4	M4K2	M4K1
Channel 0	✓	✓	✓
Channel 1	✓	✓	✓

Note: ✓: Available, -: N/A

5.19. 32-bit Timer Event Counter (T32A)

The 32-bit timer event counter (T32A) is a timer event counter that can operate as a 32-bit timer or two 16-bit timers. The option to select whether T32A operates as a 32-bit timer or a 16-bit timer is available. When the T32A operates as 32-bit timer, the T32A operates as timer C incorporating a 32-bit counter. When the T32A operates as 16-bit timer, the T32A operates as timer A and B incorporating a 16-bit counter.

The T32A has various functions such as an interval timer, event counter, input capture, 2-phase pulse count, PPG output, synchronous start, and trigger start and stop.

Table 5.18 Built-in T32A

T32A	M4K4	M4K2	M4K1
Channel 0	✓	✓	✓
Channel 1	✓	✓	✓
Channel 2	✓	✓	✓
Channel 3	✓	✓	✓
Channel 4	✓	✓	✓
Channel 5	✓	✓	✓

Note1: ✓: Available, -: N/A

Note2: External pins vary depending on the product. Refer to section "2. Pin Assignment".

5.20. Clock Selective Watchdog Timer (SIWDT)

The clock selective watchdog timer (SIWDT) is a peripheral function that detects an overflow of the counter and generates an interrupt request or reset signal. This state occurs when a counter cannot be cleared within the preset detection time because the CPU executes mal function (a runaway) caused by a noise or others.

The count clock for the counter can be selected from three clocks: system clock (fsys) of 4 division, internal high-speed oscillation clock 1 (fIHOSC1), or internal high-speed oscillation clock 2 (fIHOSC2).

It also provides the count-clear window function that can clear the binary counter only for the specified period.

Moreover, change of a register can be prohibited by setting to protected mode until the MCU is reset. (the counter can be cleared in the protection mode.)

Table 5.19 Built-in SIWDT

	M4K4	M4K2	M4K1
SIWDT	✓	✓	✓

Note: ✓: Available, -: N/A

5.21. CRC Calculation Circuit (CRC)

The TPM4K Group(1) products incorporate the hardware calculation circuit for CRC32 and CRC16.

It can be used for detecting errors by processing a memory and communication data.

Table 5.20 Built-in CRC

	M4K4	M4K2	M4K1
CRC	✓	✓	✓

Note: ✓: Available, -: N/A

5.22. RAM Parity (RAMP)

The RAM parity (RAMP) generates an even parity for one byte data at the timing of writing data to RAM and stores it to RAM at same time. The RAMP checks that the total number of 1s in the data and parity bit is even when the CPU read data in RAM. When parity errors is detected, the RAM parity interrupt occurs.

The error status and address which the error generated in can be monitored.

A parity error can be is detected in real time, since parity generating/checking is performed by the hardware.

Table 5.21 Built-in RAMP

	M4K4	M4K2	M4K1
RAMP	✓	✓	✓

Note: ✓: Available, -: N/A

5.23. Measures for Security Risk

5.23.1. Outline

TPM4K Group(1) contains two measures for security risk to prevent unauthorized access. Table 5.22, Table 5.23 and Figure 5.1 show the assumed access paths and protection targets for each operation mode.

For more information, refer to the reference manual “Flash Memory”.

(1) Security Function

The security function prohibits communication with debugging tools. It also prohibits flash writers from reading and writing to flash memory.

Table 5.22 Access Paths and Protection Targets (1)

Operation mode	Access path	Protected object
Single chip mode Single Boot mode	JTAG/SW	CPU FLASH/ROM/RAM
Flash writer mode	Flash writer	FLASH

(2) Password in RAM Transfer Command

Single boot mode is operated by sending a command via UART communication. The RAM transfer command is authenticated by the password.

Table 5.23 Access Paths and Protection Targets (2)

Operation mode	Access path	Protected object
Single Boot mode	UART	CPU FLASH/ROM/RAM

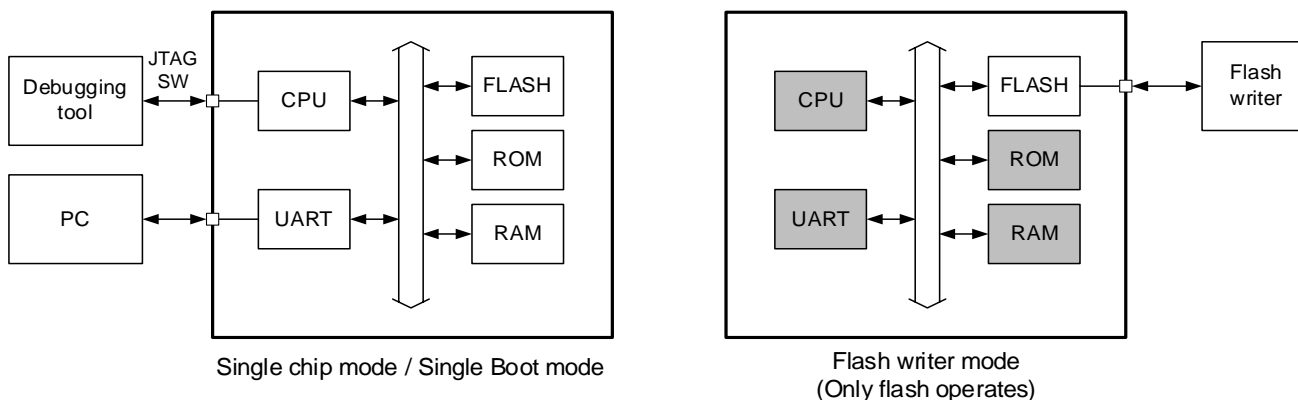


Figure 5.1 Measures for Security Risk

Note) The security function does not prohibit Non-Break Debug Interface (NBDIF) communication. Prohibit it with `[NBDICR0]<NBDEN>`.
 (It's applicable to the products with NBDIF.)

5.23.2. Disclaimer

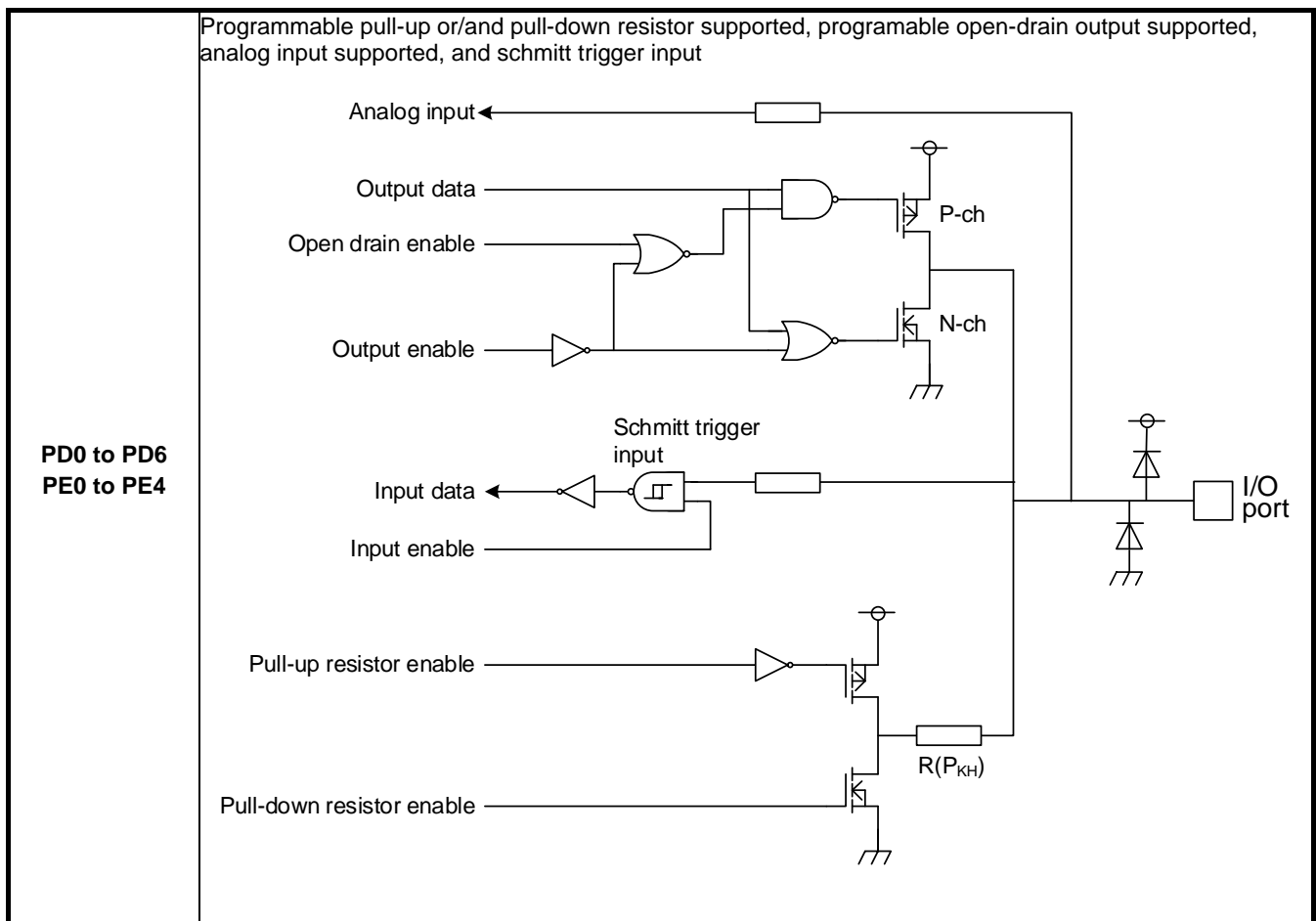
Refer to "RESTRICTIONS ON PRODUCT USE" at the end of this manual.

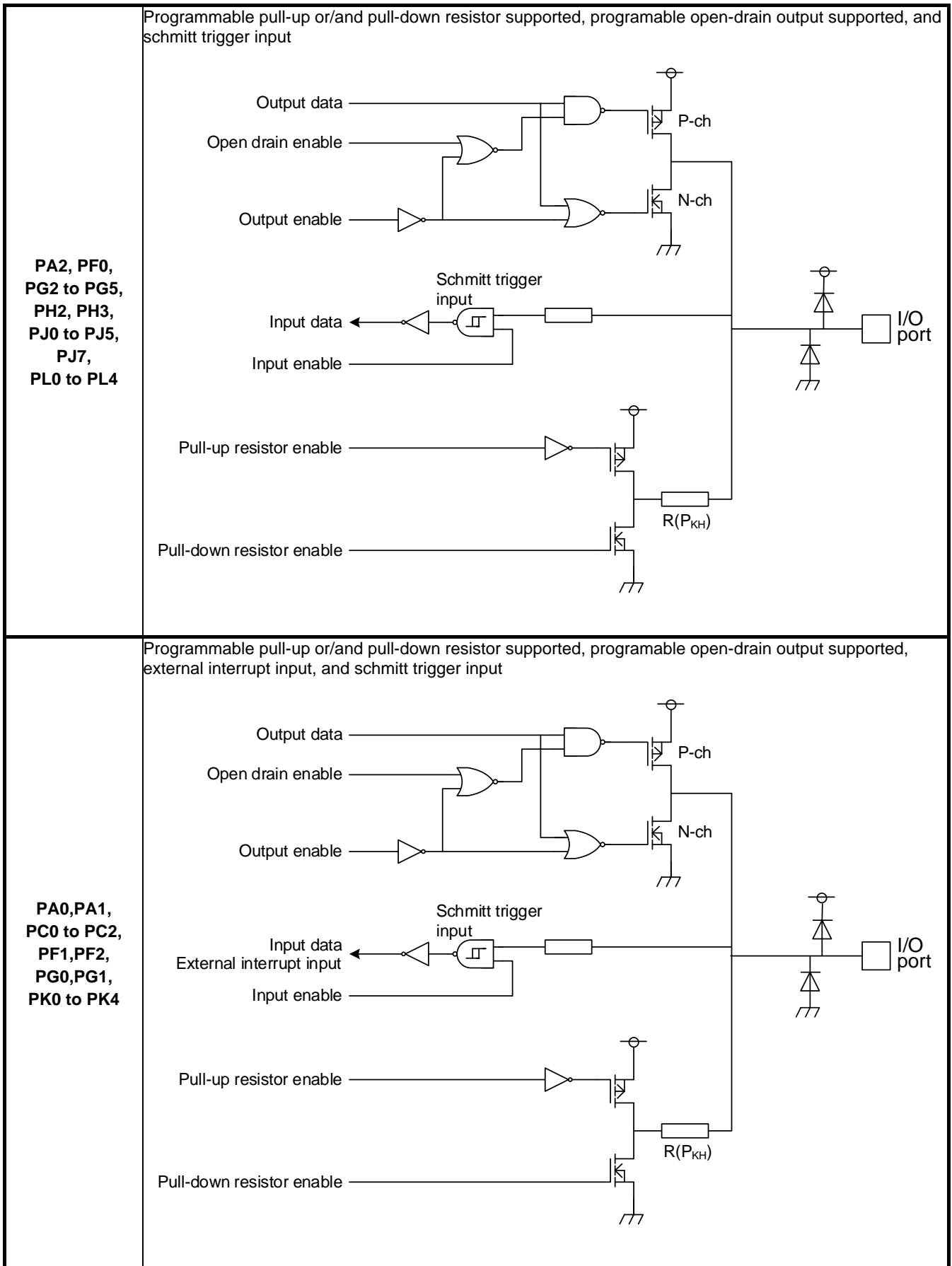
6. Equivalent Circuit

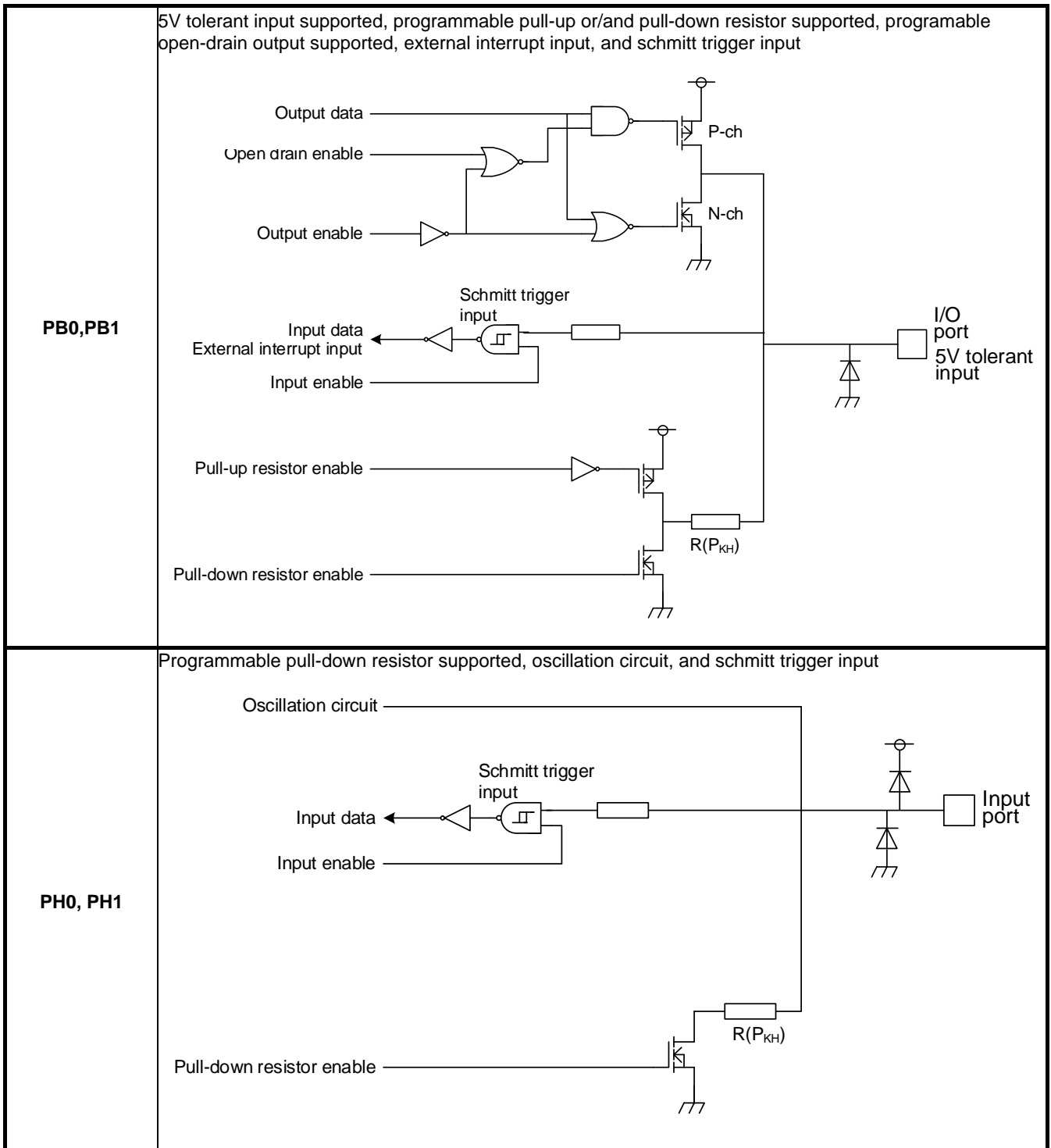
Basically, the gate symbols written are the same as those used for the standard CMOS logic IC “74HCXX” series. The input protection resistor ranges from several tens of Ω to several hundred Ω .

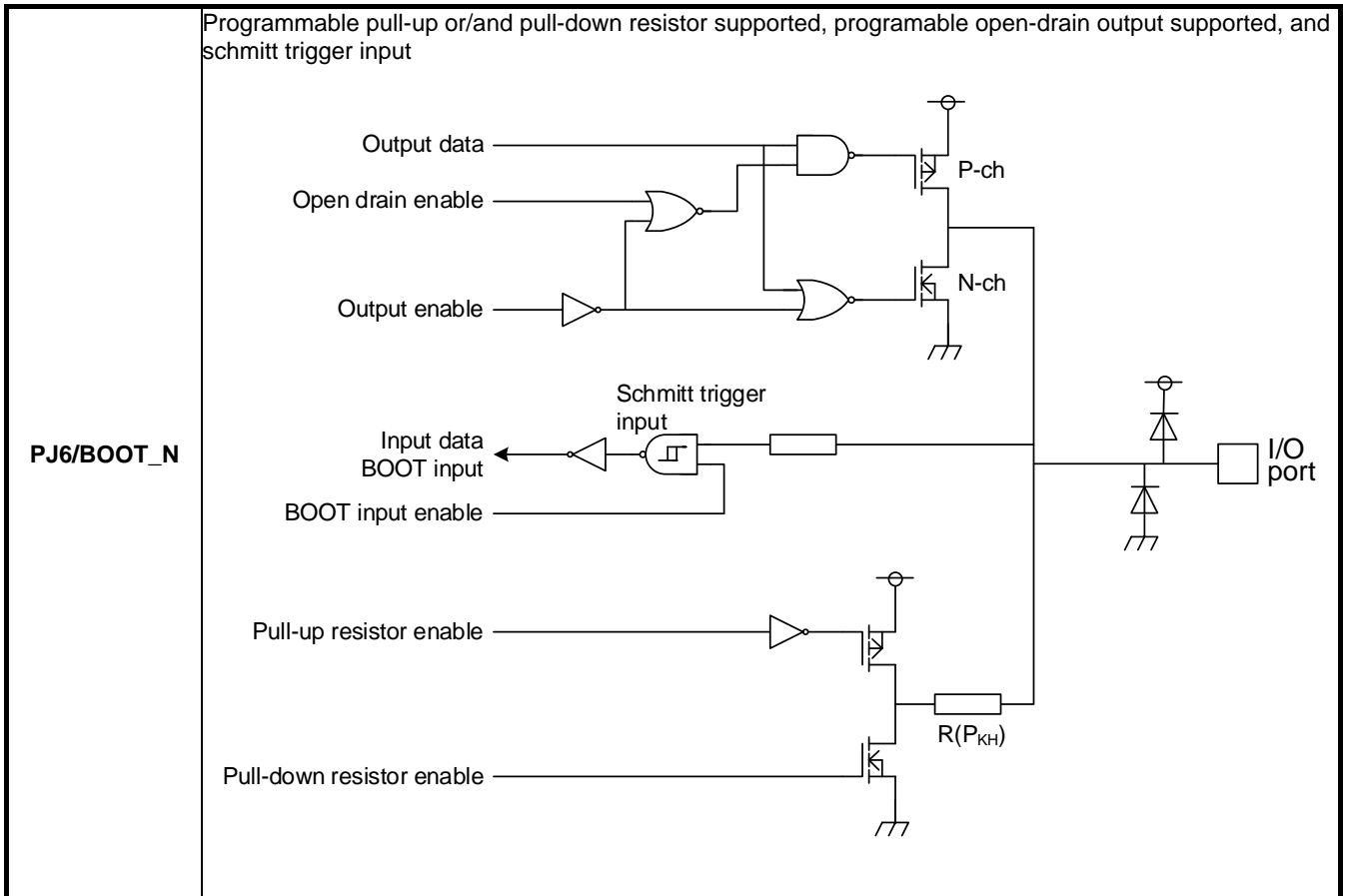
Note: The resistor without the symbol in the figure shows input protection resistor.

6.1. Port

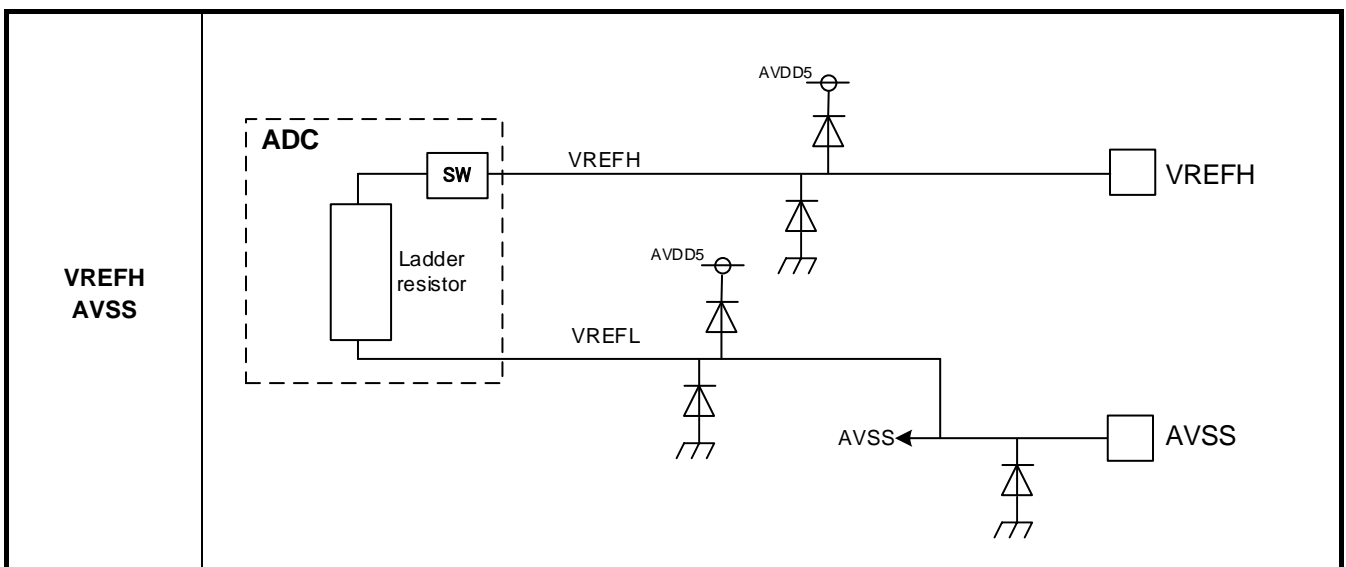






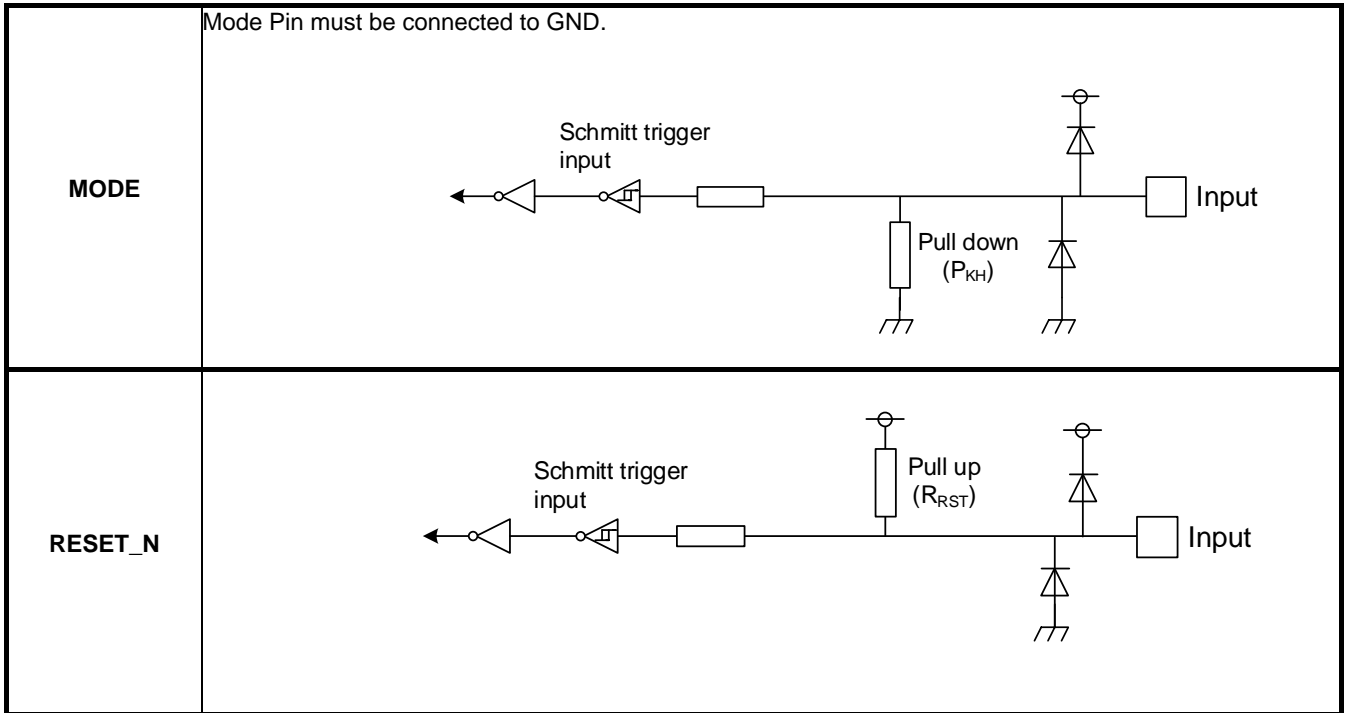


6.2. Power Supply Pin for Analog

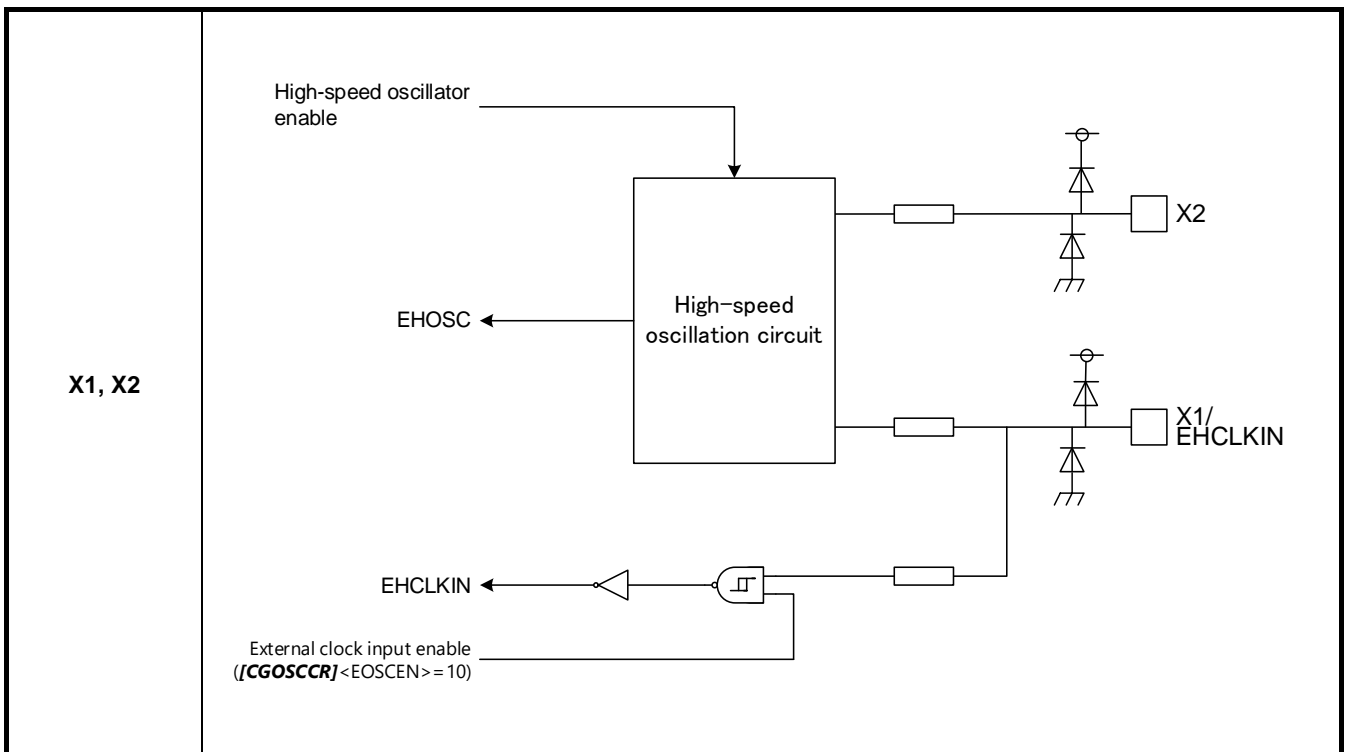


Note: SW: ON/OFF Switch Circuit

6.3. Control Pins



6.4. Clock Control Pins



7. Electrical Characteristics

7.1. Absolute Maximum Ratings

Table 7.1 Absolute Maximum Ratings

Parameter		Symbol	Rating	Unit
Power supply voltage		DVDD5A DVDD5B DVDD5C	-0.3 to 6.0	V
		AVDD5	-0.3 to 6.0	
Capacitor pin voltage for voltage maintenance		REGOUT1	-0.3 to 1.7	V
		REGOUT2	-0.3 to 3.9	
Input voltage	PA0 to PA2, PC0 to PC2, PF0 to PF2, PG0 to PG5, PH0 to PH3, PJ0 to PJ7, PK0 to PK4, PL0 to PL4, MODE, RESET_N	V_{IN1} V_{IN2}	-0.3 to DVDD5+0.3 ($\leq 6.0V$) (Note1)	V
	PD0 to PD6, PE0 to PE4	V_{IN3}	-0.3 to AVDD5+0.3 ($\leq 6.0V$)	
	PB0, PB1	V_{IN4}	-0.3 to 6.0	
Low level output current	Per pin PA0 to PA2, PC0 to PC2, PD0 to PD6, PE0 to PE4, PF0 to PF2, PG0 to PG5, PH2 to PH3, PJ0 to PJ7, PK0 to PK4, PL0 to PL4	I_{OL}	5	mA
	Per pin PB0, PB1	I_{OL4}	25	
	Total of all pins	ΣI_{OL}	50	
High level output current	Per pin PA0 to PA2, PC0 to PC2, PD0 to PD6, PE0 to PE4, PF0 to PF2, PG0 to PG5, PH2 to PH3, PJ0 to PJ7, PK0 to PK4, PL0 to PL4, PB0, PB1	I_{OH}	-5	mA
	Total of all pins	ΣI_{OH}	-50	
Power consumption		PD	500 ($T_a = 85^\circ C$) 250 ($T_a = 105^\circ C$)	mW
Soldering temperature		T_{SOLDER}	260	$^\circ C$
Storage temperature		T_{STG}	-55 to 125	$^\circ C$
Operating temperature		T_{OPR}	-40 to 105	$^\circ C$

Note1: Absolute maximum ratings are limiting values of operating and environmental conditions which should not be exceeded under the worst possible conditions. The equipment manufacturer should design so that no Absolute maximum rating value is exceeded with respect to current, voltage, power consumption, temperature, etc. Exposure to conditions beyond those listed above may cause permanent damage to the device or affect device reliability, which could increase potential risks of personal injury due to IC blow up and/or burning.

Note2: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C.

Note3: Apply the same voltage to DVDD5 and AVDD5 from power-on to power-off.

7.2. DC Electrical Characteristics (1/2)

DVDD5 = AVDD5 = 4.5 to 5.5V

DVSS = AVSS = 0V

Ta = -40 to 105°C

Parameter	Symbol	Conditions	Min	Typ.	Max	Unit
Power supply voltage	VDD	fosc = 6 to 24MHz fsys = 1 to 120MHz	4.5	-	5.5	V
Low level Input voltage	V _{IL1} V _{IL2}	-	-0.3	-	DVDD5×0.25	V
	V _{IL3}	-			AVDD5×0.25	
	V _{IL4}	-			DVDD5×0.3	
High level Input voltage	V _{IH1} V _{IH2}	-	DVDD5×0.75	-	DVDD5+0.3	V
	V _{IH3}	-			AVDD5×0.75	
	V _{IH4}	-			DVDD5×0.7	
Low level output voltage	V _{OL1} V _{OL2}	DVDD5 = 4.5V I _{OL} = 1.6mA	-	-	0.4	V
	V _{OL3}	AVDD5 = 4.5V I _{OL} = 1.6mA			0.4	
	V _{OL4}	DVDD5 = 4.5V I _{OL} = 8mA			1.0	
High level output voltage	V _{OH1} V _{OH2}	DVDD5 = 4.5V I _{OH} = -1.6mA	DVDD5-0.4	-	-	V
	V _{OH3}	AVDD5 = 4.5V I _{OH} = -1.6mA			AVDD5-0.4	

Note1: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C. DVSS is a generic name for DVSSA, DVSSB, and DVSSC.

Note2: Typ. value is in Ta = 25 °C, DVDD5 = AVDDA5 = 5.0V, unless otherwise noted.

Note3: Apply same voltage to DVDD5 and AVDD5.

$$DVDD5 = AVDD5 = 4.5 \text{ to } 5.5V$$

$$DVSS = AVSS = 0V$$

$$T_a = -40 \text{ to } 105^\circ C$$

Parameter	Symbol	Conditions	Min	Typ.	Max	Unit	
Input leak current	I_{LI}	$0.0V \leq V_{IN} \leq DVDD5$ $0.0V \leq V_{IN} \leq AVDD5$	-5	± 0.05	5	μA	
Output leak current	I_{LO}	$0.2 \leq V_{IN} \leq DVDD5 - 0.2$ $0.2 \leq V_{IN} \leq AVDD5 - 0.2$	-10	± 0.05	10		
Schmitt trigger Input width	V_{TH}	$DVDD5 = AVDD5 = 5.0V$	-	1.0	-	V	
Reset pull-up resistor	R_{RST}	-	25	50	100	k Ω	
Programmable pull-up/pull-down resistor	P_{KH}	Pull-up	25	50	100		
		Pull-down	25	50	100		
Pin capacity (except power supply pin)	C_{IO}	$f_c = 1MHz$	-	-	10	pF	
Low level output current	Per pin except PB0, PB1	I_{OL}	$DVDD5 = AVDD5 = 5.0V$	-	-	2 (Note4)	mA
	Per pin PB0, PB1	I_{OL4}	$DVDD5 = 5.0V$	-	-	12 (Note4)	
	Total of PH2, PH3, PA0 to PA2, PB0, PB1, PC0 to PC2, PJ0 to PJ7	ΣI_{OL1}	$DVDD5 = 5.0V$	-	-	35 (Note5)	
	Total of PF0 to PF2, PG0 to PG5, PK0 to PK4, PL0 to PL4	ΣI_{OL2}	$DVDD5 = 5.0V$	-	-	35 (Note5)	
	Total of PD0 to PD6, PE0 to PE4	ΣI_{OL3}	$AVDD5 = 5.0V$	-	-	20 (Note5)	
High level output current	Per pin	I_{OH}	$DVDD5 = AVDD5 = 5.0V$	-2 (Note4)	-	-	mA
	Total of PH2, PH3, PA0 to PA2, PB0, PB1, PC0 to PC2, PJ0 to PJ7	ΣI_{OH1}	$DVDD5 = 5.0V$	-35 (Note5)	-	-	
	Total of PF0 to PF2, PG0 to PG5, PK0 to PK4, PL0 to PL4	ΣI_{OH2}	$DVDD5 = 5.0V$	-35 (Note5)	-	-	
	Total of PD0 to PD6, PE0 to PE4	ΣI_{OH3}	$AVDD5 = 5.0V$	-20 (Note5)	-	-	

Note1: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C. DVSS is a generic name for DVSSA, DVSSB, and DVSSC.

Note2: Typ. value is in $T_a = 25^\circ C$, $DVDD5 = AVDDA5 = 5.0V$, unless otherwise noted.

Note3: Apply same voltage to DVDD5 and AVDD5.

Note4: The sum of the pin currents in each group should not exceed the total current of each group.

Note5: The sum of each group current should not exceed the absolute maximum rating.

DVDD5 = AVDD5 = 2.7 to 4.5V

DVSS = AVSS = 0V

Ta = -40 to 105°C

Parameter	Symbol	Conditions	Min	Typ.	Max	Unit
Power supply voltage	VDD	fosc = 6 to 24MHz fsys = 1 to 120MHz	2.7	-	4.5	V
Low level Input voltage	V _{IL1} V _{IL2}	-	-0.3	-	DVDD5×0.25	V
	V _{IL3}	-			AVDD5×0.25	
	V _{IL4}	-			DVDD5×0.3	
High level Input voltage	V _{IH1} V _{IH2}	-	DVDD5×0.75	-	DVDD5+0.3	V
	V _{IH3}	-			AVDD5×0.75	
	V _{IH4}	-			DVDD5×0.7	
Low level output voltage	V _{OL1} V _{OL2}	DVDD5 = 2.7V I _{OL} = 0.8mA	-	-	0.4	V
	V _{OL3}	AVDD5 = 2.7V I _{OL} = 0.8mA	-	-	0.4	
	V _{OL4}	DVDD5 = 2.7V I _{OL} = 4mA	-	-	1.0	
High level output voltage	V _{OH1} V _{OH2}	DVDD5 = 2.7V I _{OH} = -0.8mA	DVDD5-0.4	-	-	V
	V _{OH3}	AVDD5 = 2.7V I _{OH} = -0.8mA			AVDD5-0.4	

Note1: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C. DVSS is a generic name for DVSSA, DVSSB, and DVSSC.

Note2: Typ. value is in Ta = 25 °C, DVDD5 = AVDDA5 = 3.0V, unless otherwise noted.

Note3: Apply same voltage to DVDD5 and AVDD5.

DVDD5 = AVDD5 = 2.7 to 4.5V

DVSS = AVSS = 0V

Ta = -40 to 105°C

Parameter	Symbol	Conditions	Min	Typ.	Max	Unit	
Input leak current	I _{LI}	0.0V ≤ VIN ≤ DVDD5 0.0V ≤ VIN ≤ AVDD5	-5	±0.05	5	μA	
Output leak current	I _{LO}	0.2 ≤ VIN ≤ DVDD5-0.2 0.2 ≤ VIN ≤ AVDD5-0.2	-10	±0.05	10		
Schmitt trigger Input width	V _{TH}	DVDD5 = AVDD5 = 3.0V	-	0.5	-	V	
Reset pull-up resistor	R _{RST}	-	25	100	200	kΩ	
Programmable pull-up/pull-down resistor	P _{KH}	Pull-up	25	100	200		
		Pull-down	25	100	200		
Pin capacity (except power supply pin)	C _{IO}	fc = 1MHz	-	-	10	pF	
Low level output current	Per pin except PB0, PB1	I _{OL}	DVDD5 = AVDD5 = 3.0V	-	-	1 (Note4)	mA
	Per pin PB0, PB1	I _{OL4}	DVDD5 = 3.0V	-	-	6 (Note4)	
	Total of PJ2, PH3, PA0 to PA2, PB0, PB1, PC0 to PC2, PJ0 to PJ7	ΣI _{OL1}	DVDD5 = 3.0V	-	-	18 (Note5)	
	Total of PF0 to PF2, PG0 to PG5, PK0 to PK4, PL0 to PL4	ΣI _{OL2}	DVDD5 = 3.0V	-	-	18 (Note5)	
	Total of PD0 to PD6, PE0 to PE4	ΣI _{OL3}	AVDD5 = 3.0V	-	-	10 (Note5)	
High level output current	Per pin	I _{OH}	DVDD5 = AVDD5 = 3.0V	-1 (Note4)	-	-	mA
	Total of PH2, PH3, PA0 to PA2, PB0, PB1, PC0 to PC2, PJ0 to PJ7	ΣI _{OH1}	DVDD5 = 3.0V	-18 (Note5)	-	-	
	Total of PF0 to PF2, PG0 to PG5, PK0 to PK4, PL0 to PL4	ΣI _{OH2}	DVDD5 = 3.0V	-18 (Note5)	-	-	
	Total of PD0 to PD6, PE0 to PE4	ΣI _{OH3}	AVDD5 = 3.0V	-10 (Note5)	-	-	

Note1: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C. DVSS is a generic name for DVSSA, DVSSB, and DVSSC.

Note2: Typ. value is in Ta = 25 °C, DVDD5 = AVDDA5 = 3.0V, unless otherwise noted.

Note3: Apply same voltage to DVDD5 and AVDD5.

Note4: The sum of the pin currents in each group should not exceed the total current of each group.

Note5: The sum of each group current should not exceed the absolute maximum rating.

7.3. DC Electrical Characteristics (2/2)

7.3.1. Current Consumption

Ta = -40 to 105°C

Parameter	Symbol	Conditions	Min	Typ.	Max	Unit
NORMAL mode	IDD	Refer to the Table 7.2 and Table 7.3 for detail.	-	25.0	35.0	mA
IDLE mode			-	1.9	8.0	
STOP1 mode			-	0.23	5.50	mA

Note1: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C.

Note2: Typ. value is in Ta = 25 °C, DVDD5 = AVDDA5 = 5.0V, unless otherwise noted.

Note3: Apply same voltage to DVDD5 and AVDD5.

Note4: Input pins are fixed. Output pins are opened.

Table 7.2 IDD Measurement Condition (Pin Setting and Oscillation Circuit)

		NORMAL mode	IDLE mode	STOP1 mode
Pin setting	DVDD5 and AVDD5	5.0V (Typ.), 5.5V (max)		
	X1 and X2 pins	External high-speed oscillator connected (10MHz)		
	Input pins	Fixed		
	Output pins	Opened		
Operation condition (Oscillation circuit)	System clock (fsys)	120MHz		Stopped
	External high-speed oscillator (EHOSC)	Oscillation		Stopped
	Internal high-speed oscillator 1 (IHOSC1)	stopped		
	PLL	Operated		Stopped

Table 7.3 IDD Measurement Condition (CPU and Peripheral Function)

Peripheral function	Number of built-in peripherals	NORMAL mode	IDLE mode	STOP1 mode
CPU	1	Operated (DhrystoneVer.2.1)		Stopped
DMAC	1	Operated (Request from UART ch0 TX destination: RAM)		Stopped
ADC	2	All units operated (Conversion time: 0.73μs, Repeated conversion)		Stopped
OPAMP	1	Operated		Stopped
RAMP	1	Operated		Stopped
T32A	6	All channels operated		Stopped
A-PMD	2	All channels operated		Stopped
A-ENC32	2	All channels operated		Stopped
SIWDT	1	Operated		Stopped
UART	4	2channels operated, transmission (transfer speed: 5Mbps)		Stopped
I2C/EI2C	1		Stopped	
TSPI	4	2channels operated, transmission (transfer speed 20MHz)		Stopped
CRC	1		Stopped	
LVD	1		Stopped	
OFD	1		Stopped	
DEBUG	1		Stopped	
NBDIF	1		Stopped	
PORT	-	Operated		Stopped

7.3.2. Analog Current Consumption

Ta= -40 to 105°C

Parameter	Symbol	Conditions	Min	Typ.	Max	Unit
Analog current consumption (Includes VREF current)	I _{AVDD}	AVDD5=5.0V (Typ.), 5.5V (Max), AVSS=0V ADC (all units) and OPAMP operated	-	10.2	17.0	mA

7.4. Power Supply Voltage Fluctuation

DVSSA = DVSSB = DVSSC = AVSS = 0V
 Ta = -40 to 105°C

Parameter	Symbol	Conditions	Min	Typ.	Max	Unit
Power gradient	V _{PON}	Rising slope at power-on	0.3	-	100	mV/μs
	V _{POFF}	Falling slope at power-off	-	-	10	
Power supply fluctuation rate	V _{fr}	2.7V ≤ DVDD5 = AVDD5 ≤ 5.5V	-50	-	50	

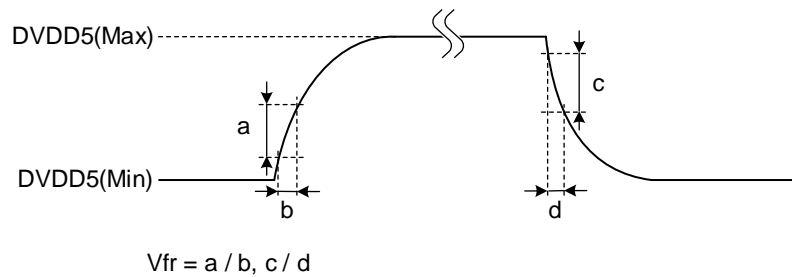


Figure 7.1 Power Supply Fluctuation Rate

Note: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C.

7.5. Characteristics of Internal Processing at RESET

DVSSA = DVSSB = DVSSC = AVSS = 0V
 Ta = -40 to 105°C

Parameter	Symbol	Conditions	Min	Typ.	Max	Unit
Internal initialized time	t _{INIT}	Power On	-	-	1.85	ms
Internal processing time for Reset	t _{IRST}	-	-	-	1.09	
Waiting time till CPU operation (Note)	t _{CPUWT}	Power-on Reset operation by LVD in STOP1 mode Reset operation by RESET_N pin in STOP1 mode	12	-	15	μs
		Reset operation by LVD in NORMAL or IDLE mode Reset operation by RESET_N pin in NORMAL or IDLE mode Reset operation by SIWDT, OFD, LOCKUP, or SYSRESET in NORMAL or IDLE mode	104	-	108	

Note: Except reset operation by SIWDT, OFD, LOCKUP, or SYSRESET, when reset factor repeats, t_{CPUWT} (Waiting time till CPU running) starts measuring elapse time after releasing this factor.

7.6. Characteristics of Power-on Reset

DVSSA = DVSSB = DVSSC = AVSS = 0V
 Ta = -40 to 105°C

Parameter	Symbol	Conditions	Min	Typ.	Max	Unit
Detection voltage	V _{PREL}	Power increases	2.22	2.33	2.44	V
	V _{PDET}	Power decreases	2.17	2.28	2.39	
Detection pulse width 1	T _{PDET1}	-	200	-	-	μs

7.7. Characteristics of PORF

DVSSA = DVSSB = DVSSC = AVSS = 0V
 Ta = -40 to 105°C

Parameter	Symbol	Conditions	Min	Typ.	Max	Unit
Detection voltage	V _{PORFL}	Power increases	2.57	2.64	2.71	V
	V _{PORFD}	Power decreases	2.52	2.59	2.66	
Detection pulse width 2	T _{PDET2}	-	200	-	-	μs

7.8. Characteristics of Voltage Detection Circuit

DVDD5 = AVDD5 = 2.7 to 5.5V

DVSS = AVSS = 0V

Ta = -40 to 105°C

Parameter	Symbol	Conditions	Min	Typ.	Max	Unit	
Detection voltage	V _{LVL0}	Power up	2.63	2.7	2.77	V	
		Power down	2.58	2.65	2.72		
	V _{LVL1}	Power up	2.68	2.75	2.82	V	
		Power down	2.63	2.7	2.77		
	V _{LVL2}	Power up	2.78	2.85	2.92	V	
		Power down	2.73	2.8	2.87		
	V _{LVL3}	Power up	2.88	2.95	3.02	V	
		Power down	2.83	2.9	2.97		
	V _{LVL4}	Power up	3.96	4.05	4.14	V	
		Power down	3.91	4.0	4.09		
	V _{LVL5}	Power up	4.16	4.25	4.34	V	
		Power down	4.11	4.2	4.29		
	V _{LVL6}	Power up	4.36	4.45	4.54	V	
		Power down	4.31	4.4	4.49		
	V _{LVL7}	Power up	4.56	4.65	4.74	V	
		Power down	4.51	4.6	4.69		
	Detection response time	t _{VDDT1}	Power down	-	-	100	μs
	Release response time	t _{VDDT2}	Power up	-	-	100	
Setup time	t _{LV DEN}	-	-	-	100		
Detection Minimum pulse width	t _{LV DPW}	-	200	-	-		

Note: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C. DVSS is a generic name for DVSSA, DVSSB, and DVSSC.

7.9. 12-bit AD Converter Characteristics

7.9.1. AD Converter Characteristics

DVDD5 = AVDD5 = 2.7 to 5.5V

DVSS = AVSS = 0V

Ta = -40 to 105°C

Parameter	Symbol	Conditions	Min	Typ.	Max	Unit	
Analog reference voltage (+)	VREFH	-	2.7	-	5.5	V	
Analog input voltage	VAIN	-	AVSS (VREFL)	-	VREFH		
Difference between analog power supply and reference voltage	$\Delta VREF$	$VREFH \leq AVDD5$	0	-	0.5		
Integral nonlinear error (INL)	-	1 unit operation $4.5V \leq AVDD5 \leq 5.5V$ $4.5V \leq VREFH \leq 5.5V$ AVSS = VREFL = 0V AIN load resistor = 600 Ω AIN load capacity $\geq 0.1\mu F$	-5	-	5	LSB	
Differential nonlinear error (DNL)			-1	-	4		
Zero-scale error			-5	-	5		
Full-scale error			-4.5	-	4		
Total errors			-8	-	8		
Integral nonlinear error (INL)	-	1 unit operation $2.7V \leq AVDD5 < 4.5V$ $2.7V \leq VREFH < 4.5V$ AVSS = VREFL = 0V AIN load resistor = 600 Ω AIN load capacity $\geq 0.1\mu F$	-5	-	5	LSB	
Differential nonlinear error (DNL)			-1	-	4		
Zero-scale error			-5	-	3		
Full-scale error			-4.5	-	4		
Total errors			-7	-	6		
Integral nonlinear error (INL)	-	2 units operation $4.5V \leq AVDD5 \leq 5.5V$ $4.5V \leq VREFH \leq 5.5V$ AVSS = VREFL = 0V AIN load resistor = 600 Ω AIN load capacity $\geq 0.1\mu F$	-5	-	8	LSB	
Differential nonlinear error (DNL)			-1	-	7		
Zero-scale error			-7	-	8		
Full-scale error			-5	-	7		
Total errors			-12	-	14		
Integral nonlinear error (INL)	-	2 units operation $2.7V \leq AVDD5 < 4.5V$ $2.7V \leq VREFH < 4.5V$ AVSS = VREFL = 0V AIN load resistor = 600 Ω AIN load capacity $\geq 0.1\mu F$	-5	-	5	LSB	
Differential nonlinear error (DNL)			-1	-	5		
Zero-scale error			-7	-	3		
Full-scale error			-5	-	6		
Total errors			-12	-	8		
SCLK frequency	f_{SCLK}	$4.5V \leq AVDD5 \leq 5.5V$	4	-	30	MHz	
		$2.7V \leq AVDD5 \leq 4.5V$	4	-	24		
Sampling time	t_{smp}	OPAMP not used.	$4.5V \leq AVDD5 \leq 5.5V$	0.2	-	-	μs
			$2.7V \leq AVDD5 < 4.5V$	0.33	-	-	
		OPAMP used.		0.4	-	-	
Conversion time	t_{conv}	OPAMP not used.	$4.5V \leq AVDD5 \leq 5.5V$	0.73	-	-	
			$2.7V \leq AVDD5 < 4.5V$	1	-	-	
Stable time	t_{sta}	After [ADAMOD0]<DACON> = 1 is set.	3	-	-		

Note1: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C. DVSS is a generic name for DVSSA, DVSSB, and DVSSC.

Note2: Typ. value is in Ta = 25 °C, DVDD5 = AVDDA5 = 5.0V, unless otherwise noted.

Note3: 1LSB = (VREFH - AVSS (VREFL)) / 4096 [V]

Note4: The ADC characteristics in the above table shows when only ADC operates.

7.9.2. Reference Power Supply

$$DVDD5 = AVDD5 = 2.7 \text{ to } 5.5\text{V}$$

$$DVSS = AVSS = 0\text{V}$$

$$T_a = -40 \text{ to } 105^\circ\text{C}$$

Parameter	Conditions	Min	Typ.	Max	Unit
Reference power supply	ch18 select	0.99	-	1.21	V

Note: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C. DVSS is a generic name for DVSSA, DVSSB, and DVSSC.

7.10. Operational Amplifier Characteristics

$$DVDD5 = AVDD5 = 4.5\text{V to } 5.5\text{V}$$

$$DVSS = AVSS = 0\text{V}$$

$$T_a = -40 \text{ to } 105^\circ\text{C}$$

Parameter	Symbol	Conditions	Min	Typ.	Max	Unit
Gain (magnification) (Note2)	VGAIN	-	2.0	-	15	times
Amplifier input voltage range (Common)	VAMPINP VAMPINN	-	AVSS-0.3	-	(AVDD5×0.97) / VGAIN	V
Amplifier input voltage range (Differential)	VAMPINP VAMPINN	Min GAIN = x 2.0	0	-	AVDD5 / (Min Gain)	
Amplifier output voltage	VVOLT	-	AVDD5×0.03	-	AVDD5 × 0.97	
Differential step offset voltage	VOFF	-	-5	-	5	mV
Gain error range	-	-	-3	-	3	%
Slew rate	Vthr	CL = 10pF	6	10	-	V/μs
AMPEN → Output stable time	t _{sta1}	Time until the amplitude of output waveform against the target is within +5mV (upper limit) and -5mV (lower limit) CL = 10pF	-	-	2	μs

Note1: The characteristic when the amplifier unit operates only.

Note2: The magnification of gain can be selected from ×2.5, ×3, ×3.5, ×4, ×4.5, ×6, ×7, ×8, ×10, and ×12.

Note3: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C. DVSS is a generic name for DVSSA, DVSSB, and DVSSC.

Note4: T_a = 25 °C, DVDD5 = AVDDA5 = 5.0V, unless otherwise noted.

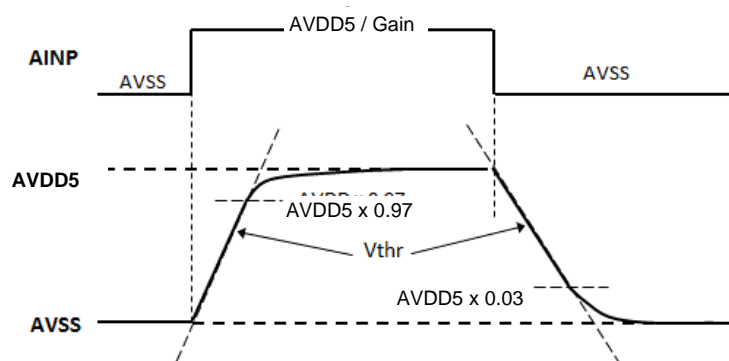


Figure 7.2 Slew Rate

7.11. AC Electrical Characteristics

The values shown in the "AC Electrical Characteristics" of this chapter do not include clock errors.
In practice, the AC characteristics can be affected by both errors (a) and (b).

- (a) Oscillation frequency error of the clock used as fosc
- (b) PLL error (maximum $\pm 3\%$)

7.11.1. Serial Peripheral Interface (TSPI)

7.11.1.1. AC Measurement Conditions

The AC characteristics are the result under the measurement conditions below:

- DVDD5 = AVDD5 = 2.7 to 5.5 V
- Ta = -40 to 105°C
- Output level: High = $0.5 \times DVDD5$, Low = $0.5 \times DVDD5$
- Input level: High = $0.5 \times DVDD5$, Low = $0.5 \times DVDD5$
- Load capacity: CL = 30pF

Note: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C. DVSS is a generic name for DVSSA, DVSSB, and DVSSC.

7.11.1.2. AC Electrical Characteristics

"T" indicates an operation clock cycle of the TSPI. This operation clock has the same cycle of the system clock (fsys). This cycle depends on the clock gear setting.

The <RXDLY> is the setting value of [TSPIxCR2]<RXDLY[2:0]> plus 1.

(1) SIO Master mode

DVDD5 = AVDD5 = 4.5 to 5.5V

Parameter	Symbol	Min	Max	Unit
TSPIxSCK output frequency	f _{CYC}	-	20	MHz
TSPIxSCK output cycle	t _{CYC}	50	-	ns
TSPIxSCK low level output pulse width	t _{WL}	(t _{CYC} / 2) - 13	-	
TSPIxSCK high level output pulse width	t _{WH}	(t _{CYC} / 2) - 13	-	
TSPIxRXD input ← TSPIxSCK rising/falling time	t _{DSU}	35-<RXDLY>×T	-	
TSPIxSCK rising/falling time → TSPIxRXD hold time	t _{DHD}	<RXDLY>×T-5	-	
TSPIxSCK rising/falling time → TSPIxTXD hold time	t _{ODLY1}	-18	-	
TSPIxSCK rising/falling time → TSPIxTXD delay time	t _{ODLY2}	-	16	

DVDD5 = AVDD5 = 2.7 to 4.5V

Parameter	Symbol	Min	Max	Unit
TSPIxSCK output frequency	f _{CYC}	-	20	MHz
TSPIxSCK output cycle	t _{CYC}	50	-	ns
TSPIxSCK low level output pulse width	t _{WL}	(t _{CYC} / 2) - 16	-	
TSPIxSCK high level output pulse width	t _{WH}	(t _{CYC} / 2) - 16	-	
TSPIxRXD input ← TSPIxSCK rising/falling time	t _{DSU}	45-<RXDLY>×T	-	
TSPIxSCK rising/falling time → TSPIxRXD hold time	t _{DHD}	<RXDLY>×T-5	-	
TSPIxSCK rising/falling time → TSPIxTXD hold time	t _{ODLY1}	-18	-	
TSPIxSCK rising/falling time → TSPIxTXD delay time	t _{ODLY2}	-	16	

(2) SIO Slave mode

DVDD5 = AVDD5 = 4.5 to 5.5V

Parameter	Symbol	Min	Max	Unit
TSPIxSCK Input frequency	f _{CYC}	-	10	MHz
TSPIxSCK Input cycle	t _{CYC}	100	-	ns
TSPIxSCK low level Input pulse width	t _{WL}	37	-	
TSPIxSCK high level Input pulse width	t _{WH}	37	-	
TSPIxRXD Input ← TSPIxSCK rising/falling time	t _{DSU}	7	-	
TSPIxSCK rising/falling edge → TSPIxRXD hold time	t _{DHD}	10	-	
TSPIxSCK rising/falling edge → TSPIxTXD hold time	t _{ODLY1}	0	-	
TSPIxSCK rising/falling edge → TSPIxTXD delay time	t _{ODLY2}	-	36	

DVDD5 = AVDD5 = 2.7 to 4.5V

Parameter	Symbol	Min	Max	Unit
TSPIxSCK Input frequency	f _{CYC}	-	10	MHz
TSPIxSCK Input cycle	t _{CYC}	100	-	ns
TSPIxSCK low level Input pulse width	t _{WL}	37	-	
TSPIxSCK high level Input pulse width	t _{WH}	37	-	
TSPIxRXD Input ← TSPIxSCK rising/falling time	t _{DSU}	7	-	
TSPIxSCK rising/falling edge → TSPIxRXD hold time	t _{DHD}	10	-	
TSPIxSCK rising/falling edge → TSPIxTXD hold time	t _{ODLY1}	0	-	
TSPIxSCK rising/falling edge → TSPIxTXD delay time	t _{ODLY2}	-	55	

(1) 1st clock edge sampling (Master)

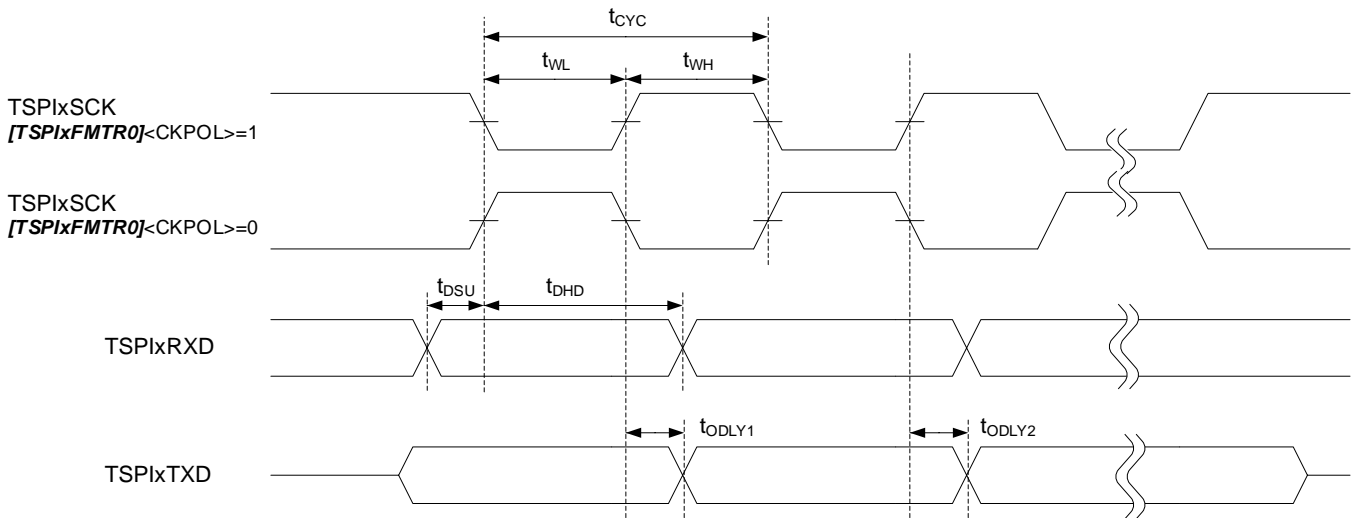


Figure 7.3 1st Clock Edge Sampling (Master)

(2) 2nd clock edge sampling (Master)

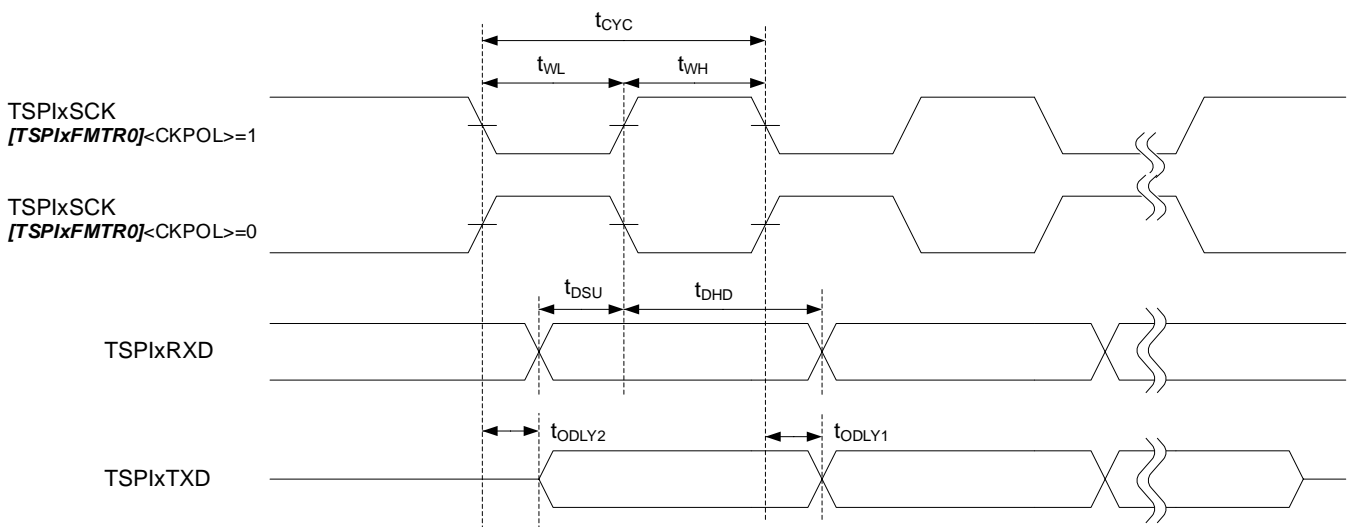


Figure 7.4 2nd Clock Edge Sampling (Master)

(3) 1st clock edge sampling (Slave)

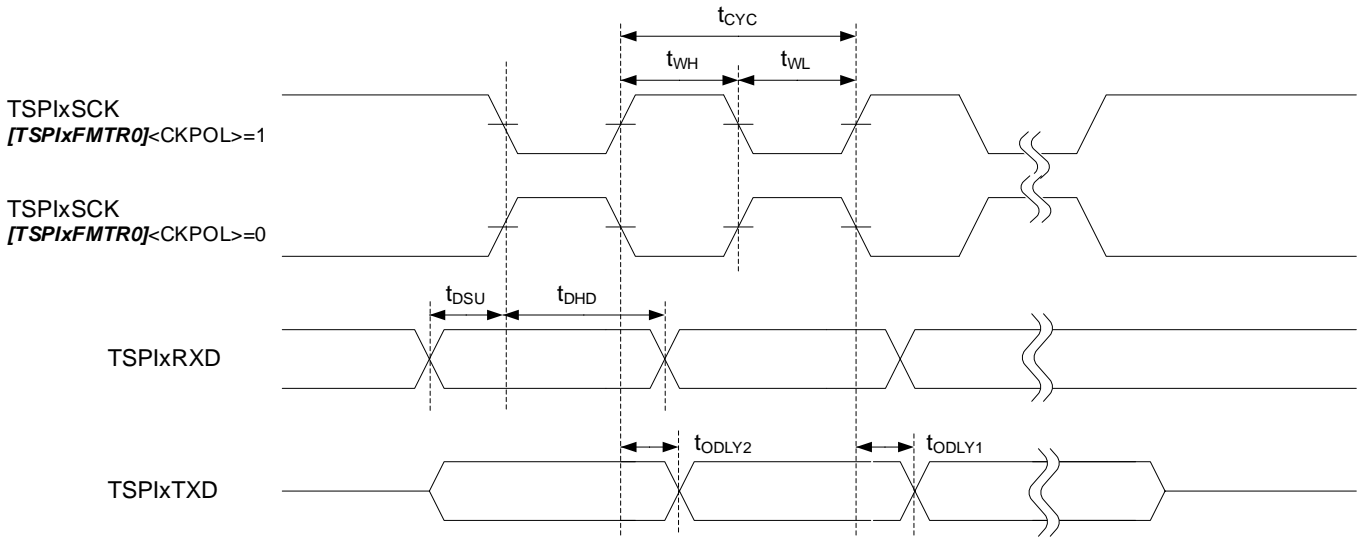


Figure 7.5 1st Clock Edge Sampling (Slave)

(4) 2nd clock edge sampling (Slave)

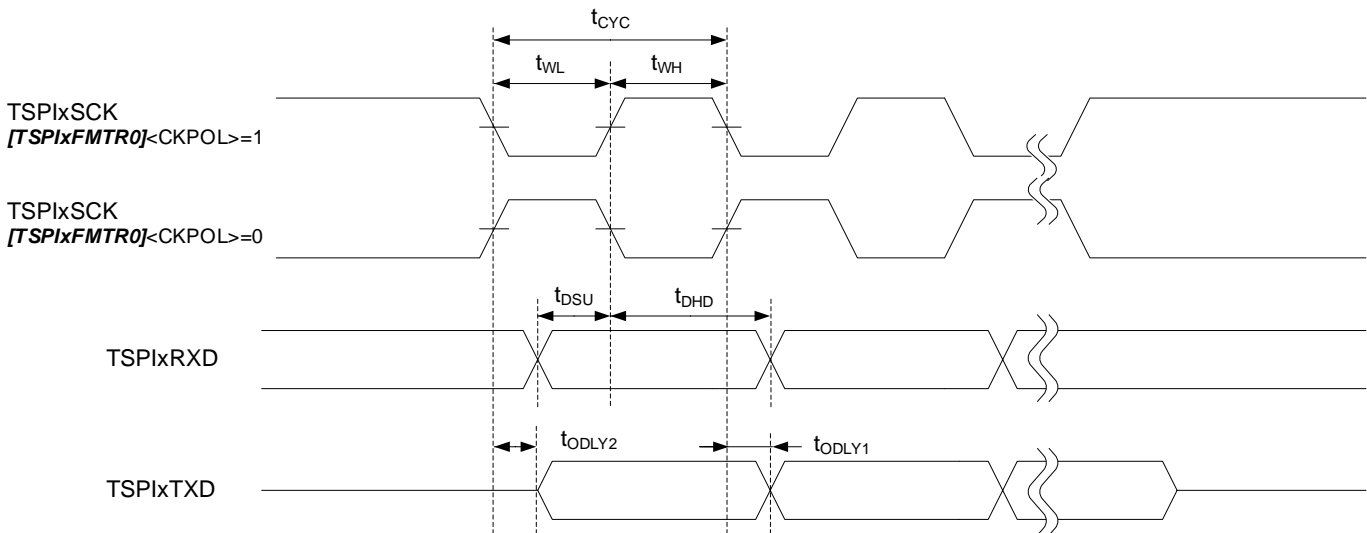


Figure 7.6 2nd Clock Edge Sampling (Slave)

7.11.2. I²C Interface (I2C)

7.11.2.1. AC Measurement Conditions

The AC characteristics are the result under the measurement conditions below:

- DVDD5 = AVDD5 = 2.7 to 5.5 V
- Ta = -40 to 105°C
- Output level: Low = 0.4V
- Input level: High = 0.7 × DVDD5, Low = 0.3 × DVDD5
- Load capacity: CL = 30pF

Note: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C. DVSS is a generic name for DVSSA, DVSSB, and DVSSC.

7.11.2.2. AC Electrical Characteristics

Parameter	Symbol	Standard mode		Fast mode		Unit
		Min	Max	Min	Max	
SCL clock frequency	f _{SCL}	0	100	0	400	kHz
Start condition hold time	t _{HD;STA}	4.0	-	0.6	-	μs
SCL clock Low width (Input) (Note1)	t _{LOW}	4.7	-	1.3	-	
SCL clock High width (Input) (Note1)	t _{HIGH}	4.0	-	0.6	-	
Re-start condition setup time	<SREN>=0 t _{SU;STA}	4.7 (Note3)	-	0.6 (Note3)	-	
	<SREN>=1 t _{SU;STA}	4.7 (Note3)	-	0.6	-	
Data hold time (Input) (Note2)	t _{HD;DAT}	0	-	0	-	ns
Data setup time	t _{SU;DAT}	250	-	100	-	
Stop condition setup time	t _{SU;STO}	4.0	-	0.6	-	
Bus free time between stop condition and start condition (Note3)	t _{BUF}	4.7	-	1.3	-	

Note1: On I²C bus standard, the maximum speed of standard mode/fast mode is 100kHz/400 kHz, respectively. For the frequency setting of the internal SCL clock, refer to the calculation formula in chapter 3.3.2 of "I2C Interface" in reference manual .

Note2: On I²C bus standard, it is described that a data internal hold time should be set at least 300 ns to avoid unstable condition on the falling of the SCL when the SDA is input; however, this precaution is not supported in this MCU. Also, the edge slope control function for the SCL is not available. Therefore, when the customer designs the MCU, make sure to follow the data hold time (input) in the table above. Note that t_r/t_f on the SCL/SDA should be included in the data hold time.

Note3: To keep the time by software.

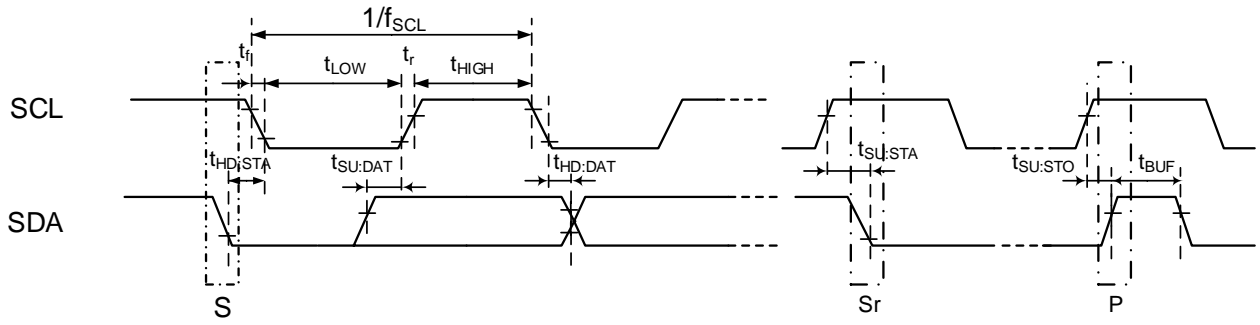


Figure 7.7 AC Timing of I2C Interface

7.11.3. I²C Interface Version A (EI2C)

7.11.3.1. AC Measurement Conditions

The AC characteristics are the result under the measurement conditions below:

- DVDD5=AVDD5= 2.7 to 5.5 V
- Ta = -40 to 105°C
- Output level: Low = 0.4V
- Input level: High = 0.7 × DVDD5, Low = 0.3 × DVDD5
- Load capacity: CL = 30pF

Note: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C. DVSS is a generic name for DVSSA, DVSSB, and DVSSC.

7.11.3.2. AC Electrical Characteristics

Parameter	Symbol	Standard mode		Fast mode		Fast mode plus		Unit
		Min	Max	Min	Max	Min	Max	
SCL clock frequency	f _{SCL}	0	100	0	400	0	1000	kHz
Start condition hold time	t _{HD;STA}	4.0	-	0.6	-	0.26	-	μs
SCL clock Low width (Input) (Note1)	t _{LOW}	4.7	-	1.3	-	0.5	-	
SCL clock High width (Input) (Note1)	t _{HIGH}	4.0	-	0.6	-	0.26	-	
Re-start condition setup time	t _{SU;STA}	4.7	-	0.6	-	0.26	-	
Data hold time (Input) (Note2)	t _{HD;DAT}	0	-	0	-	0	-	
Data setup time	t _{SU;DAT}	250	-	100	-	50	-	ns
Stop condition setup time	t _{SU;STO}	4.0	-	0.6	-	0.26	-	μs
Bus free time between stop condition and start condition (Note3)	t _{BUF}	4.7	-	1.3	-	0.5	-	

Note1: On I²C bus standard, the maximum speed of standard mode/fast mode/fast mode plus is 100kHz/400 kHz/1000kHz, respectively. For the frequency setting of the internal SCL clock, refer to the calculation formula in chapter 3.3.1 of "I²C Interface Version A" in reference manual.

Note2: On I²C bus standard, it is described that a data internal hold time should be set at least 300 ns to avoid unstable condition on the falling of the SCL when the SDA is input; however, this precaution is not supported in this MCU. Also, the edge slope control function for the SCL is not available. Therefore, when the customer designs the MCU, make sure to follow the data hold time (input) in the table above. Note that t_r/t_f on the SCL/SDA should be included in the data hold time.

Note3: To keep the time by software.

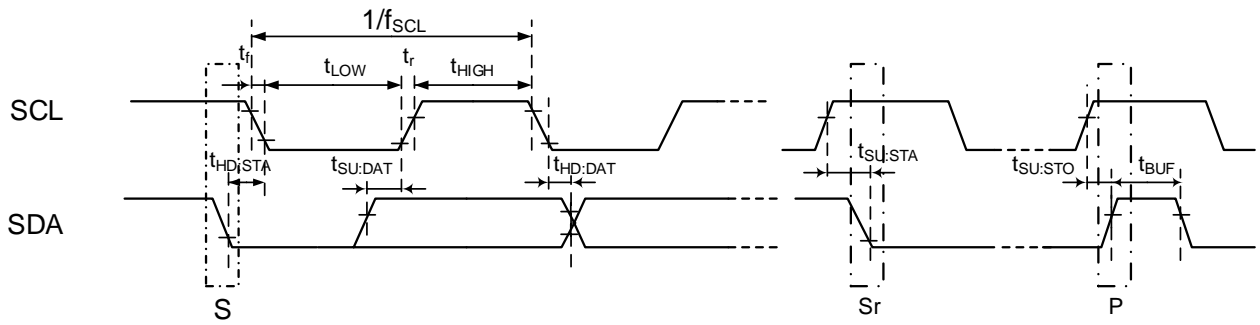


Figure 7.8 AC timing of I2C

7.11.4. 32-bit Timer Event Counter (T32A)

This section describes AC characteristics of T32AxINA0/A1, T32AxINB0/B1, and T32AxINC0/C1.

7.11.4.1. AC Measurement Conditions

The AC characteristics are the result under the measurement conditions below:

- DVDD5 = AVDD5 = 2.7 to 5.5 V
- Ta = -40 to 105°C
- Input level: High = 0.5 × DVDD5, Low = 0.5 × DVDD5

Note: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C. DVSS is a generic name for DVSSA, DVSSB, and DVSSC.

7.11.4.2. AC Electrical Characteristics

"T" in the table below indicates the operation clock cycle of the T32A. The operation clock of the T32A is the same cycle as the ΦT0 clock. This cycle is depending on the prescaler clock setting.

(1) Operation other than the pulse count

Parameter	Symbol	Min	Max	Unit
Low level pulse width	t _{VCKL}	2T + 20	-	ns
High level pulse width	t _{VCKH}	2T + 20	-	

(2) Operation at the pulse count

Parameter	Symbol	Min	Max	Unit
Pulse cycle	t _{DCYC}	1000	-	ns
Low level pulse width	t _{PWL}	500	-	
High level pulse width	t _{PWH}	500	-	
Input setup	t _{ABS}	(NF+1) × T + 20	-	
Input hold	t _{ABH}	(NF+1) × T + 20	-	

The value of NF in above table depends on the [T32AxPLSCR]<NF[1:0]> setting as follows.

[T32AxPLSCR]<NF[1:0]>	NF Value of Formula
00	0
01	2
10	4
11	8

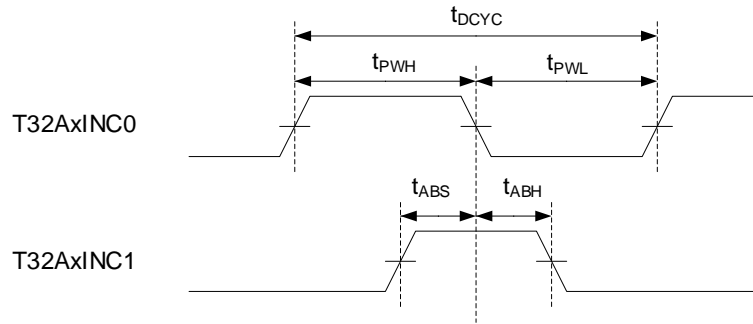


Figure 7.9 Count Pulse Input

7.11.5. External Interrupt

7.11.5.1. AC Measurement Conditions

The AC characteristics are the result under the measurement conditions below:

- DVDD5 = AVDD5 = 2.7 to 5.5 V
- Ta = -40 to 105°C
- Input level: High = 0.5 × DVDD5, Low = 0.5 × DVDD5

Note: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C. DVSS is a generic name for DVSSA, DVSSB, and DVSSC.

7.11.5.2. AC Electrical Characteristics

"T" in the table below indicates the cycle of the system clock (fsys).

(1) NORMAL and IDLE mode

Parameter	Symbol	Min	Max	Unit
Low level pulse width	t _{INTAL1}	T + 100	-	ns
High level pulse width	t _{INTAH1}	T + 100	-	

(2) STOP1 mode

Parameter	Symbol	Min	Max	Unit
Low level pulse width	t _{INTCL2}	125	-	ns
High level pulse width	t _{INTCH2}	125	-	

7.11.6. Trigger Selection Circuit (TRGSEL)

7.11.6.1. AC Measurement Conditions

The AC characteristics are the result under the measurement conditions below:

- DVDD5 = AVDD5 = 2.7 to 5.5V
- Ta = -40 to 105°C
- Input level: High = $0.5 \times DVDD5$, Low = $0.5 \times DVDD5$

Note: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C. DVSS is a generic name for DVSSA, DVSSB, and DVSSC.

7.11.6.2. AC Electrical Characteristics

"T" in the table below indicates the cycle of the system clock (fsys).

Parameter	Symbol	Min	Max	Unit
Low level pulse width	t _{ADL}	2T + 20	-	ns
High level pulse width	t _{ADH}	2T + 20	-	

7.11.7. Debug Communication

7.11.7.1. AC Measurement Conditions

The AC characteristics are the result under the measurement conditions below:

- DVDD5 = AVDD5 = 2.7 to 5.5V
- Ta = -40 to 105°C
- Output level: High = 0.5 × DVDD5, Low = 0.5 × DVDD5
- Input level: High = 0.5 × DVDD5, Low = 0.5 × DVDD5
- Load capacity: CL = 30pF

Note: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C. DVSS is a generic name for DVSSA, DVSSB, and DVSSC.

7.11.7.2. SWD Interface

DVDD5 = AVDD5 = 4.5 to 5.5V

Parameter	Symbol	Min	Max	Unit
CLK cycle	t _{dck}	100	-	ns
Output data hold from on the rising edge of CLK	t _{d1}	4	-	
Output data valid from on the rising edge of CLK	t _{d2}	-	31	
Rising edge of CLK from input data valid	t _{ds}	20	-	
Input data hold from on the rising edge of CLK	t _{dh}	15	-	

DVDD5 = AVDD5 = 2.7 to 4.5V

Parameter	Symbol	Min	Max	Unit
CLK cycle	t _{dck}	100	-	ns
Output data hold from on the rising edge of CLK	t _{d1}	4	-	
Output data valid from on the rising edge of CLK	t _{d2}	-	45	
Rising edge of CLK from input data valid	t _{ds}	20	-	
Input data hold from on the rising edge of CLK	t _{dh}	15	-	

7.11.7.3. JTAG Interface

DVDD5 = AVDD5 = 4.5 to 5.5V

Parameter	Symbol	Min	Max	Unit
CLK cycle	t_{dck}	83.3	-	ns
Output data hold from on the falling edge of CLK	t_{d3}	4	-	
Output data valid from on the falling edge of CLK	t_{d4}	-	33	
Rising edge of CLK from input data valid	t_{ds}	20	-	
Input data hold from on the rising edge of CLK	t_{dh}	15	-	

DVDD5 = AVDD5 = 2.7 to 4.5V

Parameter	Symbol	Min	Max	Unit
CLK cycle	t_{dck}	83.3	-	ns
Output data hold from on the falling edge of CLK	t_{d3}	4	-	
Output data valid from on the falling edge of CLK	t_{d4}	-	45	
Rising edge of CLK from input data valid	t_{ds}	20	-	
Input data hold from on the rising edge of CLK	t_{dh}	15	-	

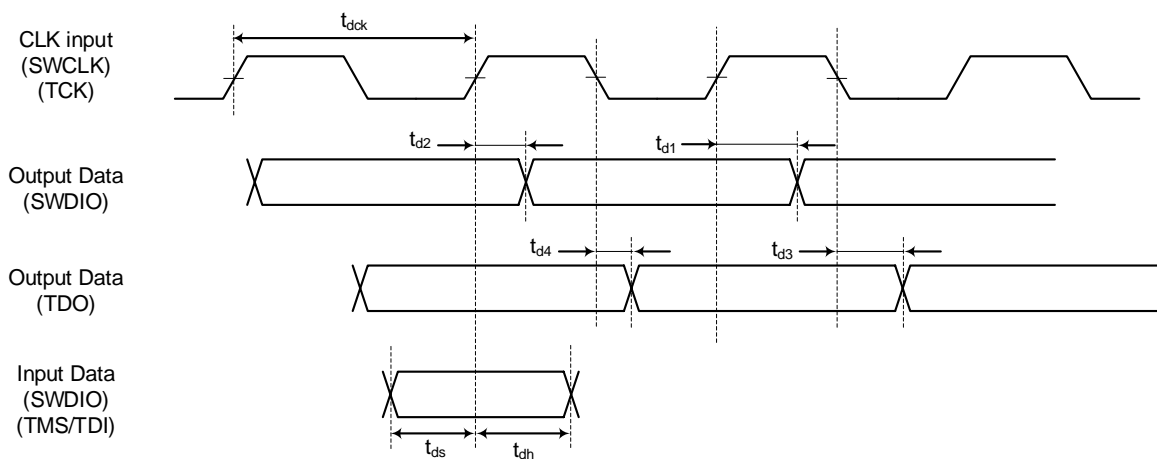


Figure 7.10 JTAG/SWD Signal Waveform

7.11.7.4. ETM Interface

DVDD5 = AVDD5 = 4.5 to 5.5V

Parameter	Symbol	Min	Max	Unit
TRACECLK cycle	t_{clk}	33.3	-	ns
Data valid from rising on TRACECLK	t_{setupr}	2	-	
TRACEDATA hold from on the rising edge of TRACECLK	t_{holdr}	1	-	
TRACEDATA valid from on the falling edge of TRACECLK	t_{setupf}	2	-	
TRACEDATA hold from on the falling edge of TRACECLK	t_{holdf}	1	-	

DVDD5 = AVDD5 = 2.7 to 4.5V

Parameter	Symbol	Min	Max	Unit
TRACECLK cycle	t_{clk}	33.3	-	ns
Data valid from rising on TRACECLK	t_{setupr}	2	-	
TRACEDATA hold from on the rising edge of TRACECLK	t_{holdr}	1	-	
TRACEDATA valid from on the falling edge of TRACECLK	t_{setupf}	2	-	
TRACEDATA hold from on the falling edge of TRACECLK	t_{holdf}	1	-	

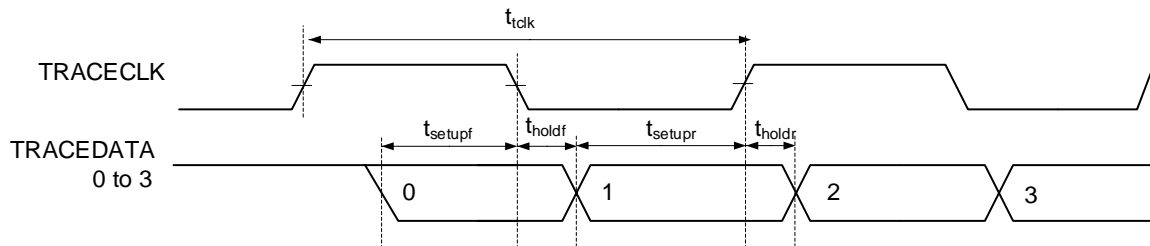


Figure 7.11 Trace Signal Waveform

7.11.8. NBD Interface

7.11.8.1. AC Measurement Conditions

The AC characteristics are the result under the measurement conditions below:

- DVDD5 = AVDD5 = 2.7 to 5.5V
- Ta = -40 to 105°C
- Output level: High = 0.5 × DVDD5, Low = 0.5 × DVDD5
- Input level: High = 0.5 × DVDD5, Low = 0.5 × DVDD5
- Load capacity: CL = 30pF

Note: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C. DVSS is a generic name for DVSSA, DVSSB, and DVSSC.

7.11.8.2. AC Electrical Characteristics

Parameter	Symbol	Min	Max	Unit
NBDCLK cycle	t_{NDCYC}	80	-	ns
NBDCLK low level pulse width	t_{NDL}	35	-	
NBDDATA output delay time	t_{NDD}	-	$t_{NDCYC} - 20$	
NBDDATA output hold time	t_{NDHD}	5	-	
NBDDATA setup time	t_{NDS}	20	-	
NBDDATA hold time	t_{NDH}	5	-	
NBDSYNC setup time	t_{NDSYS}	20	-	
NBDSYNC output hold time	t_{NDSYH}	5	-	

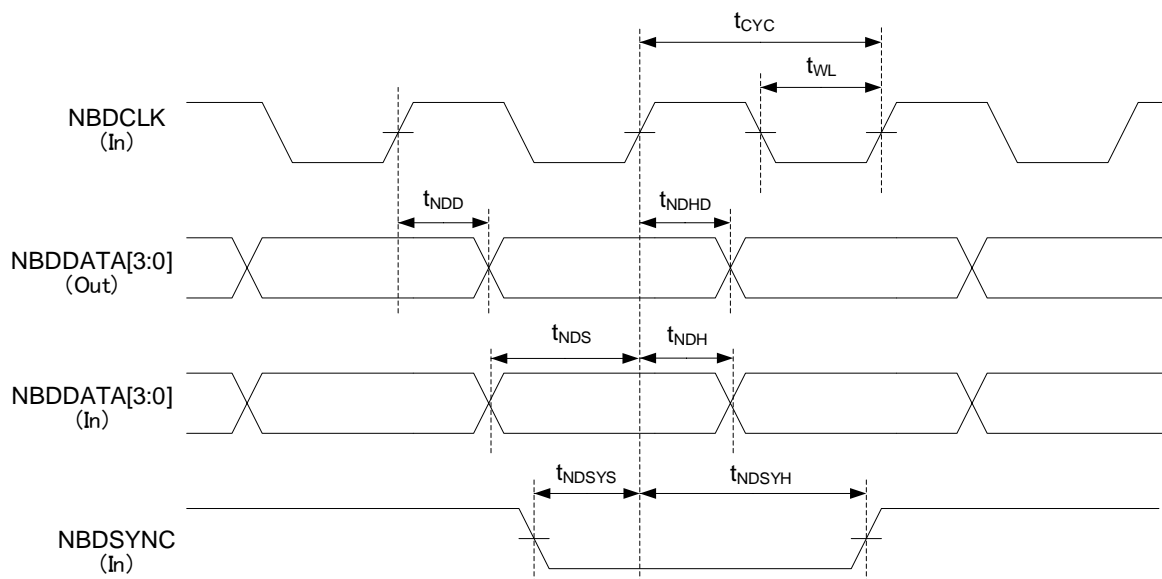


Figure 7.12 AC Timing of NBDIF

7.11.9. SCOUT Pin

7.11.9.1. AC Measurement Conditions

The AC characteristics are the result of the measurement conditions below:

- DVDD5 = AVDD5= 2.7 to 5.5V
- Ta = -40 to 105°C
- Output level: High = 0.5 × DVDD5, Low = 0.5 × DVDD5
- Load capacity: CL = 30pF

Note: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C. DVSS is a generic name for DVSSA, DVSSB, and DVSSC.

7.11.9.2. AC Electrical Characteristics

"T" in the table indicates the cycle of the SCOUT output waveform.

DVDD5 = AVDD5 = 4.5 to 5.5V

Parameter	Symbol	Min	Max	Unit
Low level pulse width	t _{sCL}	0.5 × T- 10	-	ns
High level pulse width	t _{sCH}	0.5 × T- 10	-	

DVDD5 = AVDD5 = 2.7 to 4.5V

Parameter	Symbol	Min	Max	Unit
Low level pulse width	t _{sCL}	0.5 × T- 12	-	ns
High level pulse width	t _{sCH}	0.5 × T- 12	-	

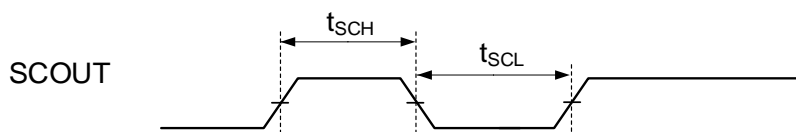


Figure 7.13 SCOUT Waveform Output

7.11.10. External Clock Input

7.11.10.1. AC Measurement Conditions

The AC characteristics are the result under the measurement conditions below:

- DVDD5 = AVDD5 = 2.7 to 5.5V
- Ta = -40 to 105°C
- Input level: High = $0.75 \times DVDD5$, Low = $0.25 \times DVDD5$

Note: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C. DVSS is a generic name for DVSSA, DVSSB, and DVSSC.

7.11.10.2. AC Electrical Characteristics

Parameter	Symbol	Min	Typ.	Max	Unit
Clock frequency ($1/t_{\text{echin}}$)	f_{EHCLKIN}	6	-	24	MHz
Clock duty	-	45	-	55	%
Clock rising time	t_r	-	-	10	ns
Clock falling time	t_f	-	-	10	ns

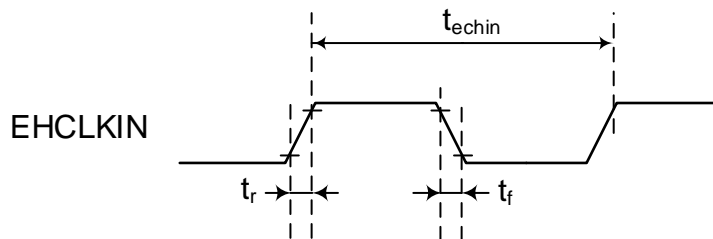


Figure 7.14 External Clock Input Waveform

7.12. Noise Filter Characteristics

DVDD5 = AVDD5 = 2.7 to 5.5V
 Ta = -40 to 105°C

Parameter	Condition	Min	Typ.	Max	Unit
Noise cancel width	-	15	30	60	ns

7.13. Flash Memory Characteristics

7.13.1. Code Flash

DVDD5 = AVDD5 = 2.7 to 5.5V
 Ta = -40 to 105°C

Parameter	Condition	Min	Typ.	Max	Unit
Rewrite frequencies	-	-	-	100,000	cycles
Programming time	Programming time for a word	-	22.6	-	μs
Erase time	Page erase time	2.1	-	8.4	ms
	Block erase time	16.8	-	67.1	
	Area erase time (Note2)	-	9.1	-	

Note1: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C. DVSS is a generic name for DVSSA, DVSSB, and DVSSC.

Note2: In case that flash memory has no block with effective protection.

7.13.2. Chip Erase

DVDD5 = AVDD5 = 2.7 to 5.5V
 Ta = -40 to 105°C

Parameter	Condition	Min	Typ.	Max	Unit
Chip erase time	Erasing of code flash, protect bits (Code), user Information area, and security bit	11.2	-	17.5	ms

Note1: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C. DVSS is a generic name for DVSSA, DVSSB, and DVSSC.

Note2: Chip erase time when flash memory has no block with effective protection.

7.14. Regulator Characteristics

DVDD5 = AVDD5 = 2.7 to 5.5V
 Ta = -40 to 105°C

Parameter	Condition	Min	Typ.	Max	Unit
Capacitance of REGOUT2 capacitor	-	0.8	4.7	5.64	μF
Capacitance of REGOUT1 capacitor		0.8	4.7	5.64	

Note: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C. DVSS is a generic name for DVSSA, DVSSB, and DVSSC.

7.15. Oscillation Circuit Characteristics

7.15.1. Internal Oscillator

DVDD5 = AVDD5 = 2.7 to 5.5V

Ta = -40 to 105°C

Parameter	Symbol	Condition	Min	Typ.	Max	Unit
Internal Oscillator 1 Oscillation frequency	f _{IHOSC1}	-	9.9	10	10.1	MHz

Note: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C. DVSS is a generic name for DVSSA, DVSSB, and DVSSC.

DVDD5 = AVDD5 = 2.7 to 5.5V

Ta = -40 to 105°C

Parameter	Symbol	Condition	Min	Typ.	Max	Unit
Internal Oscillator 2 Oscillation frequency	f _{IHOSC2}	-	9	10	11	MHz

Note: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C. DVSS is a generic name for DVSSA, DVSSB, and DVSSC.

7.15.2. External Oscillator

DVDD5 = AVDD5 = 2.7 to 5.5V

Ta = -40 to 105°C

Parameter	Symbol	Condition	Min	Typ.	Max	Unit
Oscillation frequency	f _{EHOSC}	-	6	-	24	MHz

Note1: DVDD5 is a generic name for DVDD5A, DVDD5B, and DVDD5C. DVSS is a generic name for DVSSA, DVSSB, and DVSSC.

Note2: Please contact the oscillator vendor, regarding the matching data of the device and the oscillator.

7.15.3. Oscillation Circuit

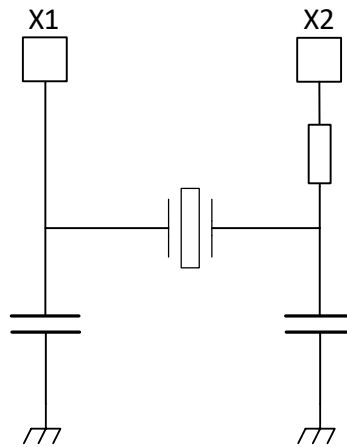


Figure 7.15 Example of Oscillation Circuit

To obtain a stable oscillation, load capacity and the position of the oscillator must be configured properly. Since these factors are strongly affected by substrate patterns, please evaluate oscillation stability using the substrate you use.

This product has been evaluated by the oscillator vendor below. Please refer this information when selecting external parts.

7.15.4. Ceramic Oscillator

This product has been evaluated by the ceramic oscillator by Murata Manufacturing Co., Ltd. Please refer to the company's website for details.

7.15.5. Crystal Oscillator

This product has been evaluated by the crystal unit by KYOCERA Corporation. Please refer to the company's website for details.

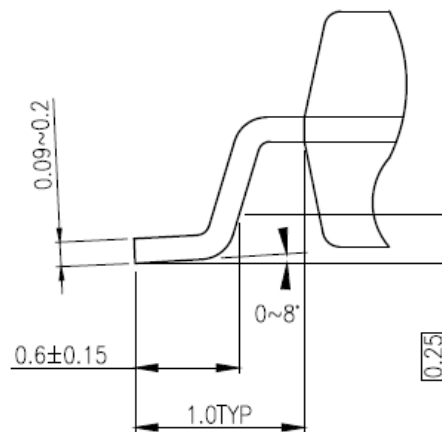
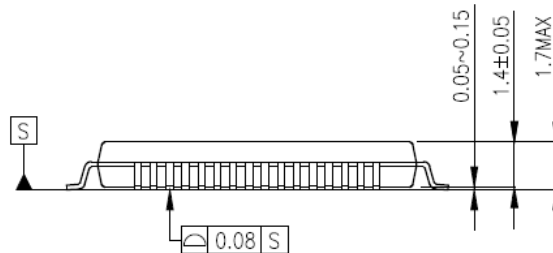
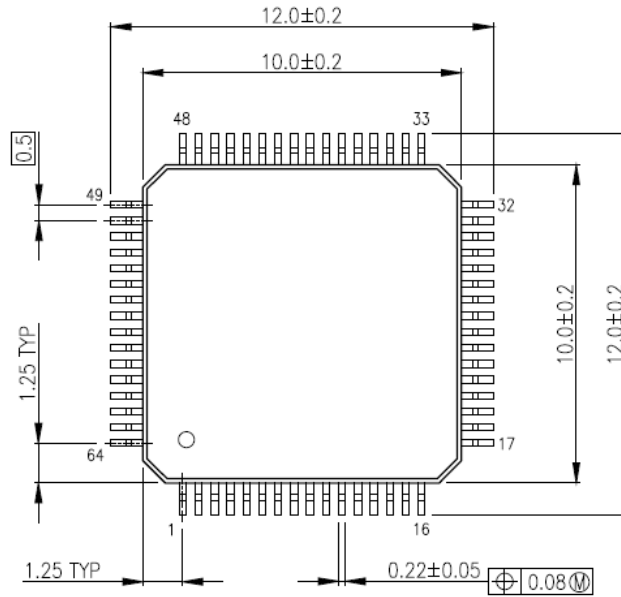
7.15.6. Precautions for Designing Printed Circuit Board

Be sure to design printed circuit board patterns that connect a crystal unit with other oscillation elements so that the length of such patterns become shortest possible to prevent deterioration of characteristics due to stray capacitances and wiring inductance. For multi-layer circuit boards, it is important not to wire the ground and other signal patterns right beneath the oscillation circuit. For more information, please refer to the URL of the oscillator vendor.

8. Package Dimensions

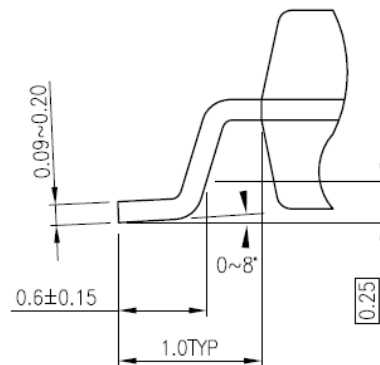
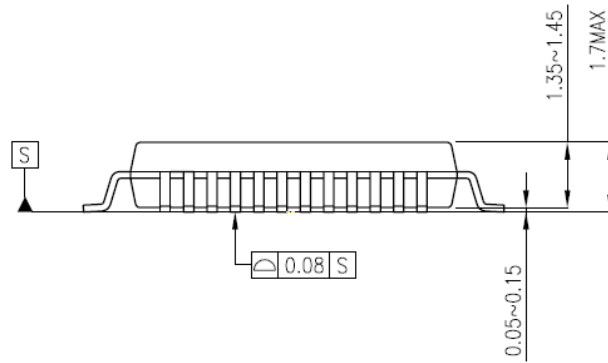
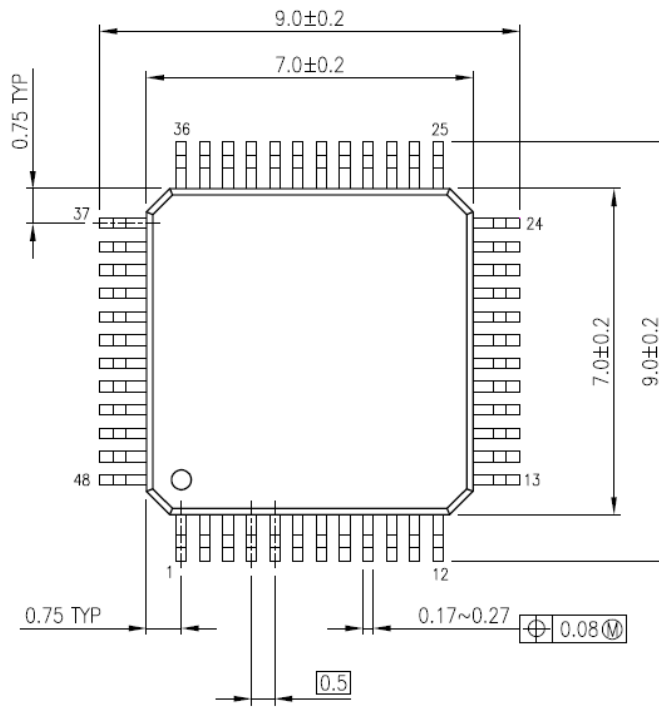
8.1. P-LQFP64-1010-0.50-003

Unit: mm



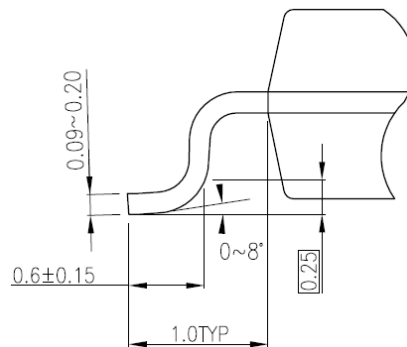
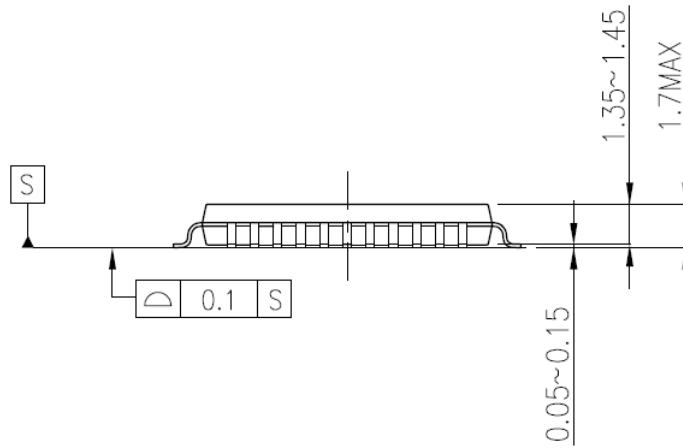
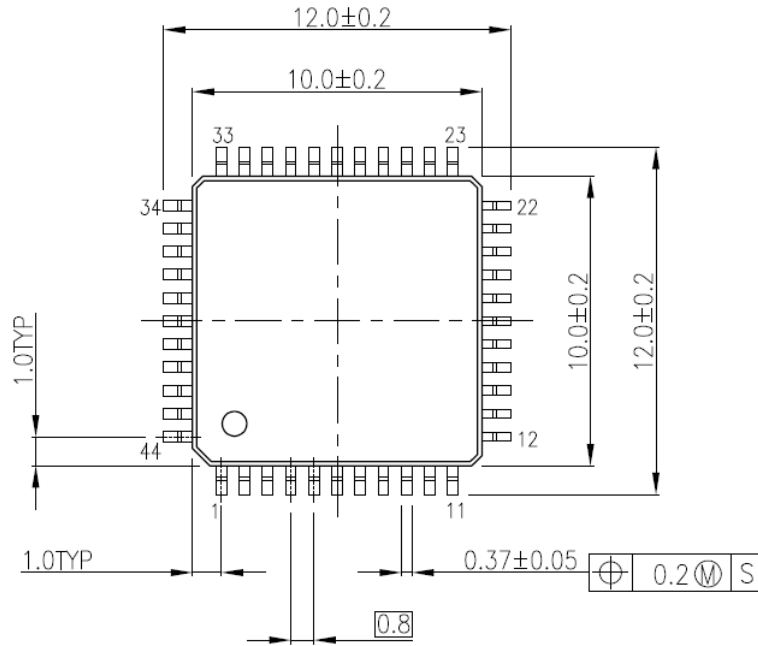
8.2. P-LQFP48-0707-0.50-002

Unit: mm



8.3. P-LQFP44-1010-0.80-003

Unit: mm



9. Precautions

This Page explains general precautions on the use of our MCUs.

Note that if there is a difference between the general precautions and the description in the body of the document, the description in the body of the document has higher priority.

(1) The MCUs' operation at power on

At power on, internal state of the MCUs is unstable. Therefore, state of the pins is undefined until reset operation is completed.

When a reset is performed by an external reset pin, pins of the MCUs that use the reset pin are undefined until reset operation by the external pin is completed.

Also, when a reset is performed by the internal power on reset, pins of the MCUs that use the internal power on reset are undefined until power supply voltage reaches the voltage at which power on reset is valid.

(2) Unused pins

Unused input/output ports of the MCUs are prohibited to use. The pins are high impedance.

Generally, if MCUs operate while the high-impedance pins left open, electrostatic damage or latch-up may occur in the internal LSI due to induced voltage influenced from external noise.

We recommend that each unused pin should be connected to the power supply pins or GND pins via resistors.

(3) Clock oscillation stability

A reset state must be released after the clock oscillation becomes stable. If the clock is changed to another clock while the program is in progress, wait until the clock is stable.

10. Revision History

Table 10.1 Revision History

Revision	Date	Description
1.0	2024-07-22	- First release
1.1	2024-11-22	- Features ·Internal memory The rewrite frequencies is changed from 10,000 to 100,000. - 7.13.1. Code Flash The rewrite frequencies in a table is changed 10,000 to 100,000.

Appendix

List of All Pins

Combination Function A and B: These are the functions which are assigned without setting port function registers.

Combination Function 1 to 8: These are the functions which are assigned with setting port function registers.

M4K4 LQFP64	M4K2 LQFP48	M4K1 LQFP44	Pin name	Combination function A	Combination function B	Combination function 1	Combination function 2	Combination function 3	Combination function 4	Combination function 5	Combination function 6	Combination function 7	Combination function 8	Input/ output	PU/PD	SV_T	SMT/ CMOS	Under reset	After reset	
1	2	1	PK2		INT02a	UT0RXD	UT0TXDA	TSPI0RXD				TMS/SWDIO		I/O	PU/PD	N/A	SMT	PU (Note1)	PU (Note1)	
2	3	2	PK3		INT03a	UT0TXDA	UT0RXD	TSPI0TXD				TCK/SWCLK		I/O	PU/PD	N/A	SMT	PD (Note1)	PD (Note1)	
3	4	3	PK4		INT06			TSPI0SCK			NBDSYNC	TRST_N		I/O	PU/PD	N/A	SMT	PU (Note1)	PU (Note1)	
4	-	-	PL3								NBDDATA3	TRACEDATA3		I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
5	-	-	PL2								NBDDATA2	TRACEDATA2		I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
6	-	-	PL1								NBDDATA1	TRACEDATA1		I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
7	-	-	PL0								NBDDATA0	TRACEDATA0		I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
8	-	-	PL4								NBDCLK	TRACECLK		I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
9	5	4	DVDD5A											-	-	-	-	-	-	
10	6	5	REGOUT2											-	-	-	-	-	-	
11	7	6	REGOUT1											-	-	-	-	-	-	
12	-	7	PH3											I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
13	8	8	PH2							EMG0				I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
14	9	9	DVSSA											-	-	-	-	-	-	
15	10	10	PH0	X1	EHCLKIN									Input	PD	N/A	SMT	Hi-Z	Hi-Z	
16	11	11	PH1	X2										Input	PD	N/A	SMT	Hi-Z	Hi-Z	
17	12	12	RESET_N											-	PU	-	SMT	-	-	
18	13	-	PA1		INT09	UT1RXD	UT1TXDA	TSPI1RXD	T32A01INA0	T32A01INC0				I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
19	14	13	PA0		INT07a	UT1TXDA	UT1RXD	TSPI1TXD	T32A01INB0	T32A01OUTB				I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
20	-	-	PA2					TSPI1SCK	T32A01INA1	T32A01INC1	T32A01OUTA	T32A01OUTC		I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
21	-	-	PJ7							OVV0				I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
22	15	14	PJ6	BOOT_N						EMG0				I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
23	16	15	PJ5						ENC1A	Z00				I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
24	17	16	PJ4						ENC1B	W00				I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
25	18	17	PJ3						ENC1Z	Y00				I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
26	19	18	PJ2							VO0				I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
27	20	19	PJ1							XO0		PMD1DBG		I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
28	21	20	PJ0							UO0	SCOUT	PMD0DBG		I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
29	22	21	DVSSB											-	-	-	-	-	-	
30	-	-	DVDD5B											-	-	-	-	-	-	
31	23	22	PB0		INT02b		UT1TXDA	I2C0SDA/ EI2C0SDA	T32A05OUTA	T32A05OUTC			PMD0DBG	UT1RXD	I/O	PU/PD	YES	SMT	Hi-Z	Hi-Z
32	24	23	PB1		INT03b	T32A05OUTB	UT1RXD	I2C0SCL/ EI2C0SCL	T32A05INA0	T32A05INC0	TRGIN1	PMD1DBG	UT1TXDA	I/O	PU/PD	YES	SMT	Hi-Z	Hi-Z	
33	-	-	PC2		INT07b			TSPI3SCK	T32A03INA1	T32A03INC1				I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
34	-	-	PC1		INT10	UT3RXD	UT3TXDA	TSPI3RXD	T32A03INA0	T32A03INC0				I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
35	25	24	PC0		INT08	UT3TXDA	UT3RXD	TSPI3TXD	T32A03OUTA	T32A03OUTC				I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
36	26	25	AVSS											-	-	-	-	-	-	
37	27	26	PD0	AINA11/ AINB11										I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
38	28	27	PD1	AINA12/ AINB12										I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
39	29	28	PD2	AINA10/ AINB10										I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
40	30	29	PD3	AINA09/ AINB09										I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
41	31	30	PD4	AINA08/ AINB08										I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
42	32	31	PD5	AINA07/ AINB07										I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
43	33	32	PD6	AINA06/ AINB06						EMG0				I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
44	34	33	PE0	AINA05/ AINB05										I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
45	35	34	PE1	AINA04/ AINB04										I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	
46	36	-	PE2	AINA03/ AINB03										I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z	

M4K4 LQFP64	M4K2 LQFP48	M4K1 LQFP44	Pin name	Combination function A	Combination function B	Combination function 1	Combination function 2	Combination function 3	Combination function 4	Combination function 5	Combination function 6	Combination function 7	Combination function 8	Input/ output	PU/PD	5V_T	SMT/ CMOS	Under reset	After reset
47	-	-	PE3	AINA02/ AINB02										I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z
48	-	-	PE4	AINA01/ AINB01										I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z
49	37	35	VREFH											-	-	-	-	-	-
50	38	36	AVDD5											-	-	-	-	-	-
51	-	-	PF2		INT01b				T32A04INA1	T32A04INC1	TRGIN2			I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z
52	-	-	PF1		INT00b				T32A04INA0	T32A04INC0				I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z
53	-	-	DVDD5C											-	-	-	-	-	-
54	39	37	DVSSC											-	-	-	-	-	-
55	40	38	PF0						T32A04OUTA	T32A04OUTC	TRGIN0	EMG1		I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z
56	41	39	PG0		INT04	UT2TXDA	TSPI2TXD	T32A02OUTA	T32A02OUTC	ENC0A	UO1	PMD0DBG		I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z
57	42	40	PG1		INT05	UT2RXD	TSPI2RXD	T32A02INA0	T32A02INC0	ENC0B	VO1	PMD1DBG		I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z
58	43	41	PG2				TSPI2SCK	T32A02INA1	T32A02INC1	ENC0Z	WO1			I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z
59	44	-	PG3								XO1			I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z
60	45	-	PG4								YO1			I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z
61	46	-	PG5								ZO1			I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z
62	47	42	MODE											-	PD	-	SMT	-	-
63	48	43	PK0		INT00a	UT0RXD	UT0TXDA		T32A00OUTA	T32A00OUTC		TDI		I/O	PU/PD	N/A	SMT	PU (Note1)	PU (Note1)
64	1	44	PK1		INT01a	UT0TXDA	UT0RXD		T32A00INA0	T32A00INC0		TDO/SWV		I/O	PU/PD	N/A	SMT	Hi-Z	Hi-Z

Note1: In the initial state, the built-in pull-up and pull-down resistors are enabled.

Note2: TRACE and NBDIF are not available in M4K2 and M4K1.

Note3: UART ch3 is not in M4K2 and M4K1.

Note4: TSPI ch1 and 3 are not in M4K2 and M4K1.

Note5: INT00b, INT01b, INT07b and INT10 are not available in M4K2 and M4K1.
 INT09 is not in M4K1.

Part Naming Conventions

TMP M4 K 4 F Y x UG

The identification of Toshiba microcontrollers

Core

Revision

Package

Symbol	Description
M4	Arm Cortex-M4 with FPU
M3	Arm Cortex-M3
M0	Arm Cortex-M0

Symbol	Description
QG	Plastic shrink quad outline non-leaded package, dry-packed
UG, DUG, FG, DFG	Plastic quad flat package, dry-packed
MG, DMG	Plastic small outline package, dry-packed
XBG	Plastic ball grid array, dry-packed

Product group

ROM Size

Family	Symbol	Main application
TXZ/ TXZ+	H	For general-purpose/consumer electronics equipment
	K	For control of motors/inverter control/industrial equipment (Analog combo)
	M	For control of motors/inverter control/industrial equipment (Analog combo), CAN built-in
	G	For OA/digital equipment/industrial equipment
	N	For industrial network/IoT information management device/Ethernet, USB, and CAN built-in
	E	For precision instrument
	L	For control of one motor/inverter control/industrial equipment
	V	For general-purpose/consumer electronics equipment (Entry Series)

Symbol	Size [KB]
M	32
P	48
S	64
U	96
W	128
Y	256
Z	384
D	512
E	768
10	1024
15	1536
20	2048

Pin count

ROM type

Symbol	Pin count	Symbol	Pin count		
0	G	32 pins or less	7	P	101 to 128 pins
1	H	33 to 44 pins	8	Q	129 to 144 pins
2	J	45 to 48 pins	9	R	145 to 176 pins
3	K	49 to 52 pins	A	S	177 to 200 pins
4	L	53 to 64 pins	B	T	201 to 224 pins
5	M	65 to 80 pins	C	U	225 to 250 pins
6	N	81 to 100 pins	D	V	251 to 300 pins

Symbol	Type
F	Flash

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